

Using the TPS546C20A Two Separated, Single-Phase Evaluation Module

The TPS546C20AEVM1-746 evaluation module (EVM) uses two TPS546C20A devices. The TPS546C20A device is a stackable synchronous buck with PMBus interface that can operate from a nominal 4.5-V to 18-V supply. The device allows programming and monitoring via the PMBus interface.

Two TPS546C20A devices are configured as two separated single phase buck converter in factory default; the negative terminals of the two outputs are connected together internally, while the positive terminals are separated.

Contents

| | | |
|----|---|----|
| 1 | Description | 3 |
| | 1.1 Typical Applications | 3 |
| | 1.2 Features | 3 |
| 2 | Electrical Performance Specifications | 4 |
| 3 | Schematic | 4 |
| 4 | Test Setup | 6 |
| | 4.1 Test and Configuration Software | 6 |
| | 4.2 Test Equipment | 6 |
| | 4.3 Recommended Test Setup | 7 |
| | 4.4 List of Test Points, Jumpers and Connectors | 8 |
| 5 | EVM Configuration Using the Fusion GUI | 10 |
| | 5.1 Configuration Procedure | 10 |
| 6 | Test Procedure | 12 |
| | 6.1 Line and Load Regulation and Efficiency Measurement Procedure | 12 |
| | 6.2 Control Loop Gain and Phase Measurement Procedure | 12 |
| | 6.3 Efficiency Measurement | 13 |
| 7 | Performance Data and Typical Characteristic Curves | 14 |
| | 7.1 Efficiency | 14 |
| | 7.2 Load Regulation | 14 |
| | 7.3 Line Regulation | 15 |
| | 7.4 Transient Response | 15 |
| | 7.5 Output Ripple | 15 |
| | 7.6 Control On | 16 |
| | 7.7 Control Off | 17 |
| | 7.8 Control On under Pre-bias | 17 |
| | 7.9 Overcurrent Protection | 18 |
| | 7.10 Control Loop Bode Plot | 18 |
| | 7.11 Thermal Image | 20 |
| 8 | EVM Assembly Drawing and PCB Layout | 21 |
| 9 | Bill of Materials | 26 |
| 10 | Screenshots | 28 |
| | 10.1 Fusion GUI Screenshots | 28 |

List of Figures

| | | |
|---|--|---|
| 1 | TPS546C20AEVM1-746 Schematic | 5 |
| 2 | TPS546C20AEVM1-746 EVM Recommended Test Set Up For Output #1 | 7 |

| | | |
|----|--|----|
| 3 | TPS546C20AEVM1-746 EVM Recommended Test Set Up For Output #2 | 7 |
| 4 | Tip and Barrel Measurement | 8 |
| 5 | Efficiency of 0.9-V Output vs Line and Load | 14 |
| 6 | Load Regulation of 0.9-V Output | 14 |
| 7 | Line Regulation of 0.9-V Output (Different Board) | 15 |
| 8 | Transient Response of 0.9-V Output at 12 V _{IN} , Transient is 10 A to 30 A, 0.2 A/μs | 15 |
| 9 | Output Ripple and SW Node of 0.9-V Output at 12 V _{IN} , 0-A Output | 15 |
| 10 | Output Ripple and SW Node of 0.9-V Output at 12 V _{IN} , 35-A Output | 16 |
| 11 | Start up from Control, 0.9-V Output at 12 V _{IN} , 0-A Output | 16 |
| 12 | Start up from Control, 0.9-V Output at 12 V _{IN} , 35-A Output | 16 |
| 13 | Soft Stop from Control, 0.9-V Output at 12 V _{IN} , 35-A Output | 17 |
| 14 | 0.6-V Pre-bias start up from Control, 0.9-V Output at 12 V _{IN} , 0-A Output | 17 |
| 15 | Overcurrent Protection, 0.9-V Output at 12 V _{IN} , 35-A Output (OC_Fault threshold is modified to 35A) | 18 |
| 16 | Bode Plot at 0.9-V Output at 12 V _{IN} , 0-A Output | 18 |
| 17 | Bode Plot at 0.9-V Output at 12 V _{IN} , 35-A Output | 19 |
| 18 | Thermal Image | 20 |
| 19 | Thermal Image | 20 |
| 20 | TPS546C20AEVM1-746 EVM 3D Top View | 21 |
| 21 | TPS546C20AEVM1-746 EVM Top Layer Assembly Drawing (Top View) | 21 |
| 22 | TPS546C20AEVM1-746 EVM Bottom Assembly Drawing (Bottom View) | 22 |
| 23 | TPS546C20AEVM1-746 EVM Top Copper (Top View) | 22 |
| 24 | TPS546C20AEVM1-746 EVM Internal Layer 1 (Top View) | 23 |
| 25 | TPS546C20AEVM1-746 EVM Internal Layer 2 (Top View) | 23 |
| 26 | TPS546C20AEVM1-746 EVM Internal Layer 3 (Top View) | 24 |
| 27 | TPS546C20AEVM1-746 EVM Internal Layer 4 (Top View) | 24 |
| 28 | TPS546C20AEVM1-746 EVM Bottom Copper (Top View) | 25 |
| 29 | Select Device Scanning Mode | 28 |
| 30 | Configure- Limits and On/Off for U1 and U2 | 30 |
| 31 | ON/OFF Control Pop-up | 31 |
| 32 | Configure - Advanced | 32 |
| 33 | Configure - SMBALERT # Mask | 33 |
| 34 | Configure - Device Info | 34 |
| 35 | Configure - All Config | 35 |
| 36 | Monitor Screen for U1 and U2 | 37 |
| 37 | Status Screen | 38 |

List of Tables

| | | |
|---|--|----|
| 1 | TPS546C20AEVM1-746 Electrical Performance Specifications | 4 |
| 2 | Test Point Functions | 8 |
| 3 | Jumpers | 9 |
| 4 | Connector Functions | 9 |
| 5 | Key Factory Configuration Parameters | 10 |
| 6 | List of Test Points for Loop Response Measurements | 12 |
| 7 | Test Points for Better Efficiency Measurements | 13 |
| 8 | TPS546C20AEVM1-746 Components List | 26 |

1 Description

The TPS546C20AEVM1-746 includes two separated buck converters. It uses a nominal 12-V bus to produce a regulated 0.9-V output and a regulated 0.95-V output at up to 35 A of load current. The TPS546C20AEVM1-746 is designed to demonstrate the TPS546C20A in a typical single phase low output voltage application while providing a number of test points to evaluate the performance of the device. The TPS546C20AEVM1-746 is NOT recommended to be modified to two-phase interleaving buck converter by changing the bill of materials (BOM). Refer to the TPS546C20A ([SLUSCK1](#)) datasheet for more information on multi-phase configuration.

1.1 Typical Applications

- High-density power solutions
- Wireless infrastructure
- Switcher
- Router Network
- Server
- Storage
- Smart power systems

1.2 Features

- One regulated 0.9-V output and another regulated 0.95-V output up to 35-A DC steady-state output current
- Both outputs are marginable and trimmable via the PMBus interface
 - Programmable UVLO, soft-start, and enable via the PMBus interface
 - Programmable overcurrent warning and fault limits and programmable response to faults via the PMBus interface
 - Programmable overvoltage and undervoltage warning and fault limits and programmable response to faults via the PMBus interface
 - Programmable turn-on and turn-off delays
- Convenient test points for probing critical waveforms

2 Electrical Performance Specifications

Table 1 lists the electrical performance specifications under room temperature 25°C.

Table 1. TPS546C20AEVM1-746 Electrical Performance Specifications

| Parameter | Test Conditions | MIN | TYP | MAX | Unit |
|---|--|-----|------|-----|---------|
| Input Characteristics | | | | | |
| Voltage range | V_{IN} | 5 | 12 | 18 | V |
| Maximum input current | $V_{IN} = 12\text{ V}$, $I_{O1} = 35\text{ A}$, $I_{O2} = 35\text{ A}$ | | 6.5 | | A |
| No load input current | $V_{IN} = 12\text{ V}$, $I_{O1} = 0\text{ A}$, $I_{O2} = 0\text{ A}$ | | 100 | | mA |
| Output Characteristics | | | | | |
| Output voltage, V_{OUT1} | | | 0.9 | | V |
| Output voltage, V_{OUT2} | | | 0.95 | | V |
| Output load current, I_{OUT1} ⁽¹⁾ | | 0 | | 35 | A |
| Output load current, I_{OUT2} ⁽¹⁾ | | 0 | | 35 | A |
| Output voltage regulation | Line Regulation: Input voltage = 5 V to 18 V | | 1% | | |
| | Load Regulation: Output current = 0 A to 35 A, both outputs | | 1% | | |
| Output voltage ripple, V_{OUT1} | $V_{IN} = 12\text{ V}$, $I_{OUT1} = 35\text{ A}$ | | 10 | | mVpp |
| Output voltage ripple, V_{OUT2} | $V_{IN} = 12\text{ V}$, $I_{OUT2} = 35\text{ A}$ | | 10 | | mVpp |
| Output Over-current Protection Threshold | Load current I_{OUT1} , default setting | | 42 | | A |
| | Load current I_{OUT2} , default setting | | 42 | | A |
| Systems Characteristics | | | | | |
| Switching frequency | $V_{IN} = 12\text{ V}$ | | 500 | | kHz |
| Full load efficiency, V_{OUT1} ⁽²⁾ | $V_{IN} = 12\text{ V}$, $I_{O1} = 35\text{ A}$, V_{OUT2} disabled | | 84% | | |
| Full load efficiency, V_{OUT2} ⁽²⁾ | $V_{IN} = 12\text{ V}$, $I_{O2} = 35\text{ A}$, V_{OUT1} disabled | | 84% | | |
| Operating temperature | T_{oper} | | 25 | | °C |
| PMBUS Interface and Pin-Strapping | | | | | |
| U1 PMBUS Address | Fixed | | 36 | | Decimal |
| U2 PMBus Address | Fixed | | 36 | | |
| U1 Voltage reference | Programmed by VSEL resistor R_{35} | | 900 | | mV |
| U2 Voltage reference | Programmed by VSEL resistor R_{36} | | 950 | | |
| U1 Soft-start time (TON_RISE) | Programmed by SS resistor R_{33} | | 5 | | ms |
| U2 Soft-start time (TON_RISE) | Programmed by SS resistor R_{37} | | 7 | | |

⁽¹⁾ The output current I_{OUT1} and I_{OUT2} can be up to 40 A, if the output overcurrent limit (IOUT_OC_FAULT_LIMIT) is set to 45 A.

⁽²⁾ The efficiency is measured based on Figure 2 and Figure 3 test setups, which includes power loss caused by on board copper traces.

3 Schematic

Figure 1 illustrates the TPS546C20AEVM1-746 EVM schematic.

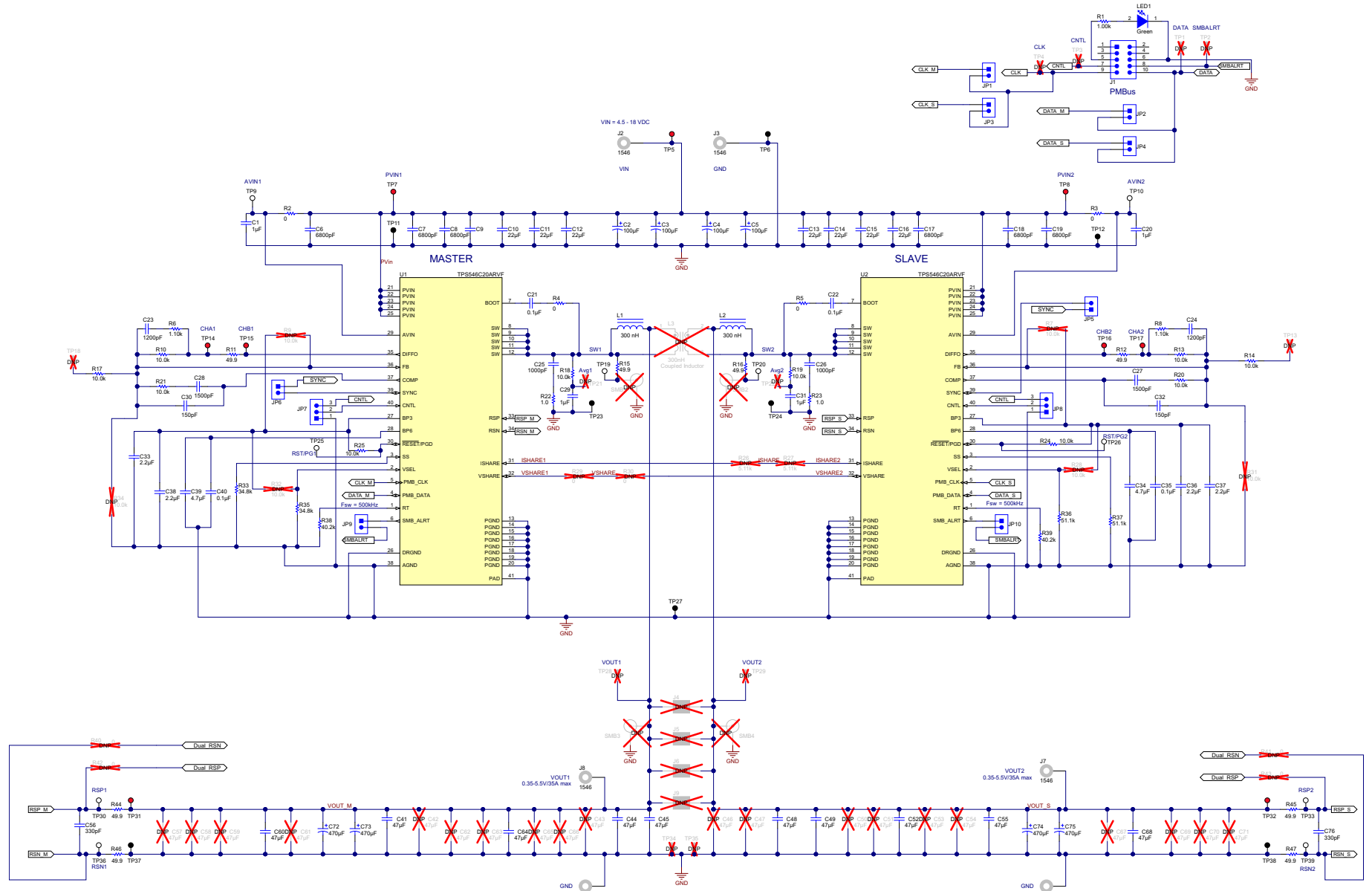


Figure 1. TPS546C20AEVM1-746 Schematic

4 Test Setup

4.1 Test and Configuration Software

In order to change any of the default configuration parameters on the EVM, it is necessary to obtain the TI Fusion Digital Power Designer software.

4.1.1 Description

The Fusion Digital Power Designer is the graphical user interface (GUI) used to configure and monitor the Texas Instruments TPS546C20A power converter installed on this evaluation module. The application uses the PMBus protocol to communicate with the controller over serial bus by way of a TI USB adapter. This adapter can be purchased at <http://www.ti.com/tool/usb-to-gpio>. (see).

4.1.2 Features

Some of the tasks you can perform with the GUI include:

- Turn on or off the power supply output, either through the hardware control line or the PMBus operation command.
- Monitor real-time data. Items such as output voltage, output current, die temperature, warnings and faults which are continuously monitored and displayed by the GUI.
- Configure common operating characteristics such as V_{OUT} trim and margin, UVLO, soft-start time, warning and fault thresholds, fault response, and ON/OFF modes.

This software is available for download at this location:

http://www.ti.com/tool/fusion_digital_power_designer

4.2 Test Equipment

4.2.1 Voltage Source

The input voltage source V_{IN} should be a 0-V to 20-V variable DC source capable of supplying 20 ADC. Connect input VIN and GND to J2 and J3 as shown in [Figure 2](#) and [Figure 3](#).

4.2.2 Multimeters

It is recommended to use two separate multi-meters as shown in [Figure 2](#) and [Figure 3](#). One meter to measure V_{IN} , the other to measure V_{OUT1} or V_{OUT2} . If both output is enabled at same time, three separate multi-meters are recommended.

4.2.3 Output Load:

A variable electronic load is recommended for the test setup as shown in [Figure 2](#) or [Figure 3](#). The load should be capable of 40 A.

4.2.4 Oscilloscope

An oscilloscope is recommended for measuring output noise and ripple. Output ripple should be measured using a *Tip-and-Barrel* method or better as shown in [Figure 4](#).

4.2.5 Fan:

During prolonged operation at high loads, it may be necessary to provide forced air cooling with a small fan aimed at the EVM. The temperature of the devices on the EVM should be maintained at less than 105°C.

4.2.6 USB-to-GPIO Interface Adapter:

A communications adapter is required between the EVM and the host computer. This EVM was designed to use the Texas Instruments USB-to-GPIO Adapter, see . This adapter can be purchased here: <http://www.ti.com/tool/usb-to-gpio>.

4.2.7 Recommended Wire Gauge

- Input VIN and GND to J2 and J3 (GND) (12-V input) – The recommended wire size is AWG #12, with the total length of wire less than 4 feet (2 feet input, 2 feet return).
- Output1 to J8 and J10 (GND) (0.9-V output) – The minimum recommended wire size is AWG #10, with the total length of wire less than 4 feet (2 feet OUTPUT, 2 feet return).
- Output2 to J7 and J11 (GND) (0.95-V output) – The minimum recommended wire size is AWG #10, with the total length of wire less than 4 feet (2 feet OUTPUT, 2 feet return).

4.3 Recommended Test Setup

Figure 2 and Figure 3 shows the recommended test setup.

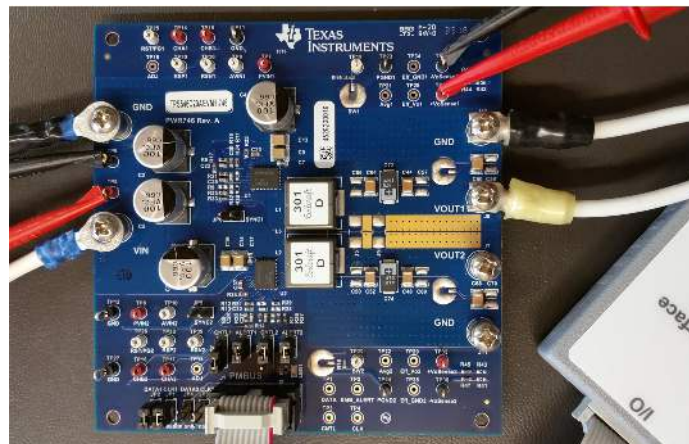


Figure 2. TPS546C20AEVM1-746 EVM Recommended Test Set Up For Output #1

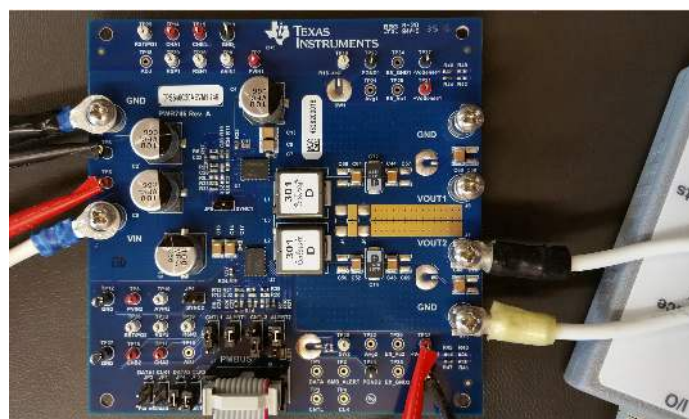


Figure 3. TPS546C20AEVM1-746 EVM Recommended Test Set Up For Output #2

Figure 4 illustrates the tip and barrel measurement for switching node waveform on TP19 with TP23 or TP20 with TP24.

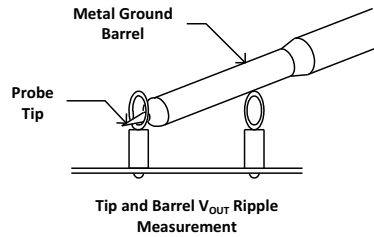


Figure 4. Tip and Barrel Measurement

4.4 List of Test Points, Jumpers and Connectors

Table 2 lists the test point functions.

Table 2. Test Point Functions

| Test Point | Type | Name | Description |
|------------|---------------|-----------|--|
| TP1 | Not Assembled | DATA | DATA signal on J1 socket |
| TP2 | Not Assembled | SMB_ALERT | SMBALERT signal on J1 socket |
| TP3 | Not Assembled | CNTL | CNTL signal on J1 socket |
| TP4 | Not Assembled | CLK | CLK signal on J1 socket |
| TP5 | T-H Loop | VIN | V _{IN+} measurement point |
| TP6 | T-H Loop | GND | V _{IN-} measurement point |
| TP7 | T-H Loop | PVIN1 | PVIN pin voltage of U1 device measurement point |
| TP8 | T-H Loop | PVIN2 | PVIN pin voltage of U2 device measurement point |
| TP9 | T-H Loop | AVIN1 | AVIN pin voltage of U1 device measurement point |
| TP10 | T-H Loop | AVIN2 | AVIN pin voltage of U2 device measurement point |
| TP11 | T-H Loop | GND | GND reference |
| TP12 | T-H Loop | GND | GND reference |
| TP13 | Not Assembled | ADJ | Analog input to adjust rail 2 output voltage |
| TP14 | T-H Loop | CHA1 | Input for small signal loop gain measurements for output rail 1 (B/A setup) |
| TP15 | T-H Loop | CHB1 | OUTPUT for small signal loop gain measurements for output rail 1 (B/A setup) |
| TP16 | T-H Loop | CHB2 | OUTPUT for small signal loop gain measurements for output rail 2 (B/A setup) |
| TP17 | T-H Loop | CHA2 | Input for small signal loop gain measurements for output rail 2 (B/A setup) |
| TP18 | Not Assembled | ADJ | Analog input to adjust rail 1 output voltage |
| TP19 | T-H Loop | SW1 | Switching node of output rail 1 measurement point, reference to TP23 |
| TP20 | T-H Loop | SW2 | Switching node of output rail 2 measurement point, reference to TP24 |
| TP21 | Not Assembled | AVG1 | Rail 1 switching node average voltage measurement point, reference to TP23 |
| TP22 | Not Assembled | AVG2 | Rail 2 switching node average voltage measurement point, reference to TP24 |
| TP23 | T-H Loop | PGND1 | GND reference for switching node measurement |
| TP24 | T-H Loop | PGND2 | GND reference for switching node measurement |
| TP25 | T-H Loop | RST/RG1 | PGOOD signal of output 1 |
| TP26 | T-H Loop | RST/PG2 | PGOOD signal of output 2 |
| TP27 | T-H Loop | GND | GND reference |
| TP28 | Not Assembled | EFF_VO1 | Rail 1 output voltage measurement point for efficiency, reference to TP34 |
| TP29 | Not Assembled | EFF_VO2 | Rail 2 output voltage measurement point for efficiency, reference to TP35 |
| TP30 | T-H Loop | RSP1 | Output 1 remote sense + voltage point |

Table 2. Test Point Functions (continued)

| Test Point | Type | Name | Description |
|------------|---------------|-----------|--|
| TP31 | T-H Loop | +VOSENSE1 | V_{OUT1+} measurement point |
| TP32 | T-H Loop | +VOSENSE2 | V_{OUT2+} measurement point |
| TP33 | T-H Loop | RSP2 | Output 2 remote sense + voltage point |
| TP34 | Not Assembled | EFF_GND1 | Rail 1 output voltage referencing GND for efficiency measurement |
| TP35 | Not Assembled | EFF_GND2 | Rail 1 output voltage referencing GND for efficiency measurement |
| TP36 | T-H Loop | RSN1 | Output 1 remote sense - voltage point |
| TP37 | T-H Loop | -VOSENSE1 | V_{OUT1-} measurement point |
| TP38 | T-H Loop | -VOSENSE2 | V_{OUT2-} measurement point |
| TP39 | T-H Loop | RSN2 | Output 2 remote sense - voltage point |

Table 3 lists the EVM jumpers.

Table 3. Jumpers

| Jumper | Type | Name | Description |
|--------|---------------------|--------|---|
| JP1 | Header, 100mil, 2x1 | CLK1 | PMBUS CLK connection between U1 and socket J1. Jumper is plugged as default. |
| JP2 | Header, 100mil, 2x1 | DATA1 | PMBUS DATA connection between U1 and socket J1. Jumper is plugged as default. |
| JP3 | Header, 100mil, 2x1 | CLK2 | PMBUS CLK connection between U2 and socket J1. Jumper is NOT plugged as default . |
| JP4 | Header, 100mil, 2x1 | DATA2 | PMBUS DATA connection between U2 and socket J1. Jumper is NOT plugged as default . |
| JP5 | Header, 100mil, 2x1 | SYNC2 | Synchronization connection between U1 and U2. Jumper is NOT plugged as default. |
| JP6 | Header, 100mil, 2x1 | SYNC1 | Synchronization connection between U1 and U2. Jumper is NOT plugged as default. |
| JP7 | Header, 100mil, 3x1 | CNTL1 | PMBUS CNTL connection options for U1 to socket J1 or GND. Jumper connecting U1 to J1 is plugged as default. |
| JP8 | Header, 100mil, 3x1 | CNTL2 | PMBUS CNTL connection options for U2 to socket J1 or GND. Jumper connecting U1 to J1 is plugged as default. |
| JP9 | Header, 100mil, 2x1 | ALERT1 | PMBUS SMBALERT connection between U1 and socket J1. Jumper is plugged as default. |
| JP10 | Header, 100mil, 2x1 | ALERT2 | PMBUS SMBALERT connection between U2 and socket J1. Jumper is plugged as default. |

Table 4 lists the EVM connector functions.

Table 4. Connector Functions

| Connector | Type | Name | Description |
|-----------|---------------------|-------|------------------------------------|
| J1 | Header, 100mil, 5x2 | PMBUS | PMBUS socket for TI FUSION adaptor |
| J2 | Keystone 1546 | VIN | VIN+ connector |
| J3 | Keystone 1546 | GND | VIN- (GND) connector |
| J8 | Keystone 1546 | VOUT1 | VOUT1+ connector |
| J10 | Keystone 1546 | GND | VOUT1- connector |
| J7 | Keystone 1546 | VOUT2 | VOUT2+ connector |
| J11 | Keystone 1546 | GND | VOUT2- connector |

5 EVM Configuration Using the Fusion GUI

The TPS546C20A on this EVM leave the factory pre-configured. See [Table 5](#) for a short list of key factory configuration parameters as obtained from the configuration file.

Table 5. Key Factory Configuration Parameters

| ADDRESS HEX | ADDRESS DEC | PART ID | DESIGNATOR | | |
|--------------------------|--------------|-------------|--|------|--|
| 0x44 | 36 | TPS546C20A | U1 | | |
| 0x44 | 36 | TPS546C20A | U2 | | |
| GENERAL | | | | | |
| CMD Code | CMD CODE HEX | ENCODED HEX | DECODED | | COMMENTS |
| VIN_OFF | 0x36 | 0xF010 | 4.0 V | | Turn OFF voltage |
| VIN_ON | 0x35 | 0xF012 | 4.5 V | | Turn ON voltage |
| IOUT_CAL_OFFSET | 0x39 | 0xE000 | 0.0000 A | | Current offset for PMBUS readout |
| IOUT_OC_FAULT_LIMIT | 0x46 | 0xF854 | 42 A | | OC fault level |
| IOUT_OC_FAULT_RESPONSE | 0x47 | 0xFF | Restart | | Response to OC fault |
| IOUT_OC_WARN_LIMIT | 0x4A | 0xF84A | 37 A | | OC warning level |
| VOUT_COMMAND | 0x21 | 0x0133 | 0.6 V | | Reference voltage |
| VOUT_MIN | 0x2B | 00B3h | 0.35V | | minimum reference voltage |
| VOUT_MAX | 0x24 | 0x034D | 1.65 V | | maximum reference voltage |
| VOUT_TRANSITION_RATE | 0x27 | 0xD03C | 1 mV/us | | Vout transition rate |
| VOUT_SCALE_LOOP | 0x29 | 0xF004 | 1 | | Output sense scaling ratio for main control loop |
| PCT_OV_UV_WRN_FLT_LIMITS | 0xD6 | 0x00 | UV FAULT | 83% | Output OV/UV Settings, reference to nominal reference voltage. |
| | | | UV WARN | 88% | |
| | | | OV WARN | 112% | |
| | | | OV FAULT | 117% | |
| VOUT_OV_FAULT_RESPONSE | 0x41 | 0xBF | Restart | | Output overvoltage fault response |
| VOUT_UV_FAULT_RESPONSE | 0x45 | 0xBF | Restart | | Output undervoltage fault response |
| ON_OFF_CONFIG | 0x02 | 0x16 | CNTL only, Active High. | | Control signal and operation command |
| OPERATION | 0x01 | 0x00 | Operation is not used to enable regulation | | Can be used to control device On/Off |
| OT_FAULT_LIMIT | 0x4F | 0x0091 | 145°C | | OT fault level |
| OT_WARN_LIMIT | 0x51 | 0x0078 | 120°C | | OT warn level |
| OT_FAULT_RESPONSE | 0x50 | 0x3F | Ignore | | Response to over temperature faults |
| TON_DELAY | 0x60 | 0x0000 | 0 ms | | Turn-on delay |
| TON_RISE | 0x61 | 0x0003 | 3 ms | | Soft-start time |
| TON_MAX_FAULT_LIMIT | 0x62 | 0x0000 | Disabled | | Upper limit for Vout reaching regulation |
| TOFF_DELAY | 0x64 | 0x0000 | 0 ms | | Turn-off delay |
| TOFF_FALL | 0x65 | 0x0000 | 0 ms | | Soft-stop fall time |

If it is desired to configure the EVM to settings other than the factory settings shown above, the TI Fusion Digital Power Designer software can be used for reconfiguration. It is necessary to have input voltage applied to the EVM prior to launching the software so that the TPS546C20A may respond to the GUI and the GUI can recognize the device. The default configuration for the EVM is to start converting at an input voltage of 4.5V, therefore to avoid any converter activity during configuration, an input voltage less than 4.5 V should be applied. An input voltage of 4 V is recommended.

5.1 Configuration Procedure

1. Adjust the input supply to provide 4 VDC, current limited to 1 A.
2. Apply the input voltage to the EVM. Refer to [Figure 2](#) and [Figure 3](#) for connections and test setup.
3. Launch the Fusion GUI software. Refer to the screenshots in [Section 10](#) for more information.
4. Configure the EVM operating parameters as desired.
5. VSEL and SS pin resistors on the EVM would program VOUT_COMMAND and TON_RISE at power up. By default, device would ignore the values stored in the internal non-volatile memory and write corresponding registers with the resistor programmed value. If **DIS_VSEL** bit in **OPTIONS (MFR_SPECIFIC_21) (E5h)** is modified to 1 (default 0), the initial VOUT_COMMAND would be same as the value stored in the internal non-volatile memory. Please see Datasheet for more details.

By default, both TPS546C20A is configured as loop master, both PMBUS address is fixed to 36 decimal.

While both device can be enabled to operate simultaneously, in order to avoid communication errors, only one device should be tied to PMBUS interface.

To configure or monitor device U1, JP1, JP2 and JP9 should be plugged in while JP3, JP4 and JP10 should be removed. Vice versa, to configure or monitor device U2, JP3, JP4 and JP10 should be plugged in while JP1, JP2 and JP9 should be removed.

6 Test Procedure

6.1 Line and Load Regulation and Efficiency Measurement Procedure

1. Set up the EVM as described in [Figure 2](#).
2. Ensure the electronic loads is set to draw 0 Adc.
3. Increase V_{IN} from 0 V to 12 V using voltage meter to measure input voltage.
4. Use the other voltage meter to measure output voltage V_{OUT1} .
5. Vary the load from 0 to 35 Adc. V_{OUT1} should remain in regulation as defined in [Table 1](#).
6. Vary V_{IN} from 5 V to 18 V. V_{OUT1} should remain in regulation as defined in [Table 1](#).
7. Decrease the load to 0 A.
8. Decrease V_{IN} to 0 V.
9. Set up the EVM as described in [Figure 3](#)
10. Increase V_{IN} from 0 V to 12 V using voltage meter to measure input voltage.
11. Use voltage meter to measure output voltage V_{OUT2} .
12. Vary the load from 0 to 35 Adc. V_{OUT2} should remain in regulation as defined in [Table 1](#).
13. Vary V_{IN} from 5 V to 18 V. V_{OUT2} should remain in regulation as defined in [Table 1](#).
14. Decrease the load to 0 A.
15. Decrease V_{IN} to 0 V.

6.2 Control Loop Gain and Phase Measurement Procedure

The TPS546C20AEVM1-746 EVM includes a 49.9- Ω series resistor in the feedback loop for both V_{OUT1} and V_{OUT2} . These resistors are used for loop response analysis, and are accessible at the test points TP14 / TP15 for V_{OUT1} , and TP16 / TP17 for V_{OUT2} . Those test points should be used during loop response measurements as the injection points for the loop perturbation. See the description in [Table 6](#).

Table 6. List of Test Points for Loop Response Measurements

| Test Point | Node Name | Description | Comment |
|------------|-----------|---|---|
| TP14 | CHA1 | Input to feedback divider of V_{OUT1} | The amplitude of the perturbation at this node should be limited to less than 30 mV |
| TP15 | CHB1 | Resulting output of V_{OUT1} | Bode can be measured by a network analyzer with a CH-B/CH-A configuration |
| TP17 | CHA2 | Input to feedback divider of V_{OUT2} | The amplitude of the perturbation at this node should be limited to less than 30 mV |
| TP16 | CHB2 | Resulting output of V_{OUT2} | Bode can be measured by a network analyzer with a CH-B/CH-A configuration |

Measure only one output at a time, with the following procedure:

1. Set up the EVM as described in [Figure 2](#).
2. For V_{OUT1} , connect the network analyzer's isolation transformer from TP14 to TP15,
3. Connect the input signal measurement probe to TP14. Connect the output signal measurement probe to TP15.
4. Connect the ground leads of both probe channels to TP11.
5. On the network analyzer, measure the Bode as TP15/TP14 (Out/In).
6. Set up the EVM as described in [Figure 3](#)
7. For V_{OUT2} , connect the network analyzer's isolation transformer from TP17 to TP16.
8. Connect the input signal measurement probe to TP17. Connect output signal measurement probe to TP16.
9. Connect the ground leads of both probe channels to TP12.
10. On the network analyzer, measure the Bode as TP16/TP17 (Out/In).

6.3 Efficiency Measurement

In order to evaluate the efficiency of the power train (device and inductor), it is important to measure the voltages at the correct location. This is necessary because otherwise the measurements will include losses that are not related to the power train itself. Losses incurred by the voltage drop in the copper traces and in the input and output connectors are not related to the efficiency of the power train, and they should not be included in efficiency measurements.

When measuring the efficiency of V_{OUT1} , disable V_{OUT2} through Jumper JP8 (Figure 2). Likewise, when measuring the efficiency of V_{OUT2} , disable V_{OUT1} through Jumper JP7 (Figure 3).

Input current can be measured at any point in the input wires, and output current can be measured anywhere in the output wires of the output being measured.

Table 7 shows the measurement points for input voltage and output voltage. VIN1 and VOUT1 are measured to calculate the efficiency of U1 rail; VIN2 and VOUT2 are measured to calculate the efficiency U2 rail. Using these measurement points will result in efficiency measurements that excluded losses due to the connectors and PCB traces.

Table 7. Test Points for Better Efficiency Measurements

| Test Point | Node Name | Description | Comment |
|--------------|-----------|---|--|
| VOUT1 | | | |
| TP7 | PVIN1 | Input voltage measurement point for VIN1+ | The pair of test points are connected to the PVIN/GND pins of U1. The voltage drop between input terminal to the device pins is excluded for efficiency measurement. |
| TP23 | PGND1 | Input voltage measurement point for VIN1- (GND) | |
| TP28 | Eff_Vo1 | Output voltage measurement point for VOUT1+ | The pair of test points are connected to the closest points of Vout /GND to the inductor. The voltage drop from the output point of inductor to the output terminals is excluded for efficiency measurement. |
| TP34 | Eff_GND1 | Output voltage measurement point for VOUT1- (GND) | |
| VOUT2 | | | |
| TP8 | PVIN2 | Input voltage measurement point for VIN2+ | The pair of test points are connected to the PVIN/GND pins of U2 . The voltage drop between input terminal to the device pins is excluded for efficiency measurement. |
| TP24 | PGND2 | Input voltage measurement point for VIN2- (GND) | |
| TP29 | Eff_Vo2 | Output voltage measurement point for VOUT2+ | The pair of test points are connected to the closest points of Vout /GND to the inductor. The voltage drop from the output point of inductor to the output terminals is excluded for efficiency measurement. |
| TP35 | Eff_GND2 | Output voltage measurement point for VOUT2- (GND) | |

7 Performance Data and Typical Characteristic Curves

Figure 5 through Figure 18 present typical performance curves for the TPS546C20AEM1-746 .

7.1 Efficiency

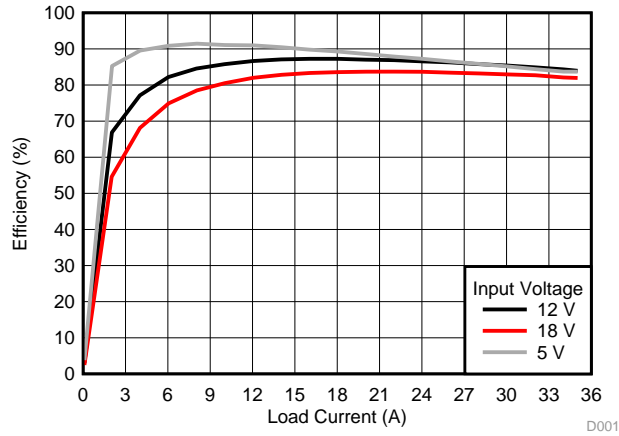


Figure 5. Efficiency of 0.9-V Output vs Line and Load

7.2 Load Regulation

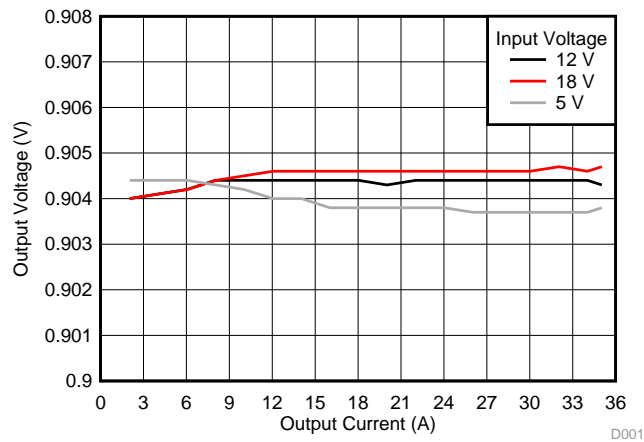


Figure 6. Load Regulation of 0.9-V Output

7.3 Line Regulation

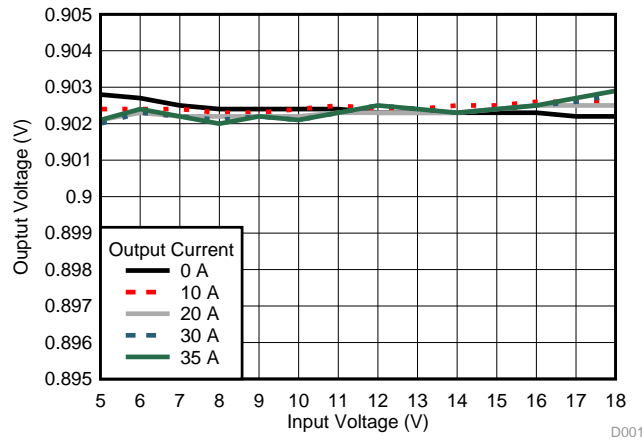
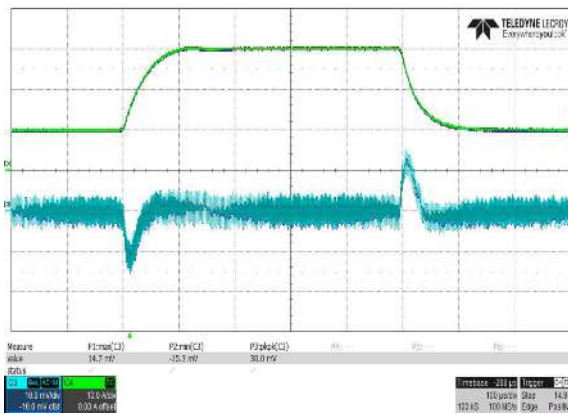


Figure 7. Line Regulation of 0.9-V Output (Different Board)

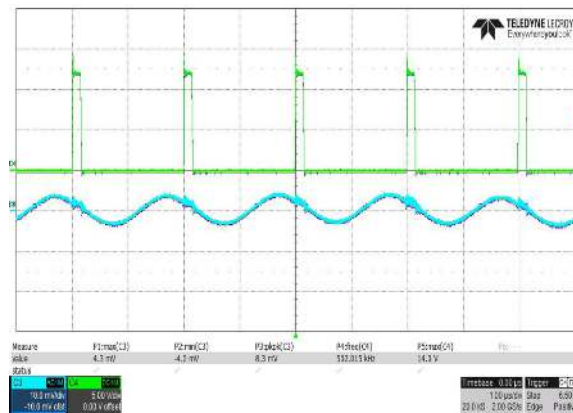
7.4 Transient Response



Ch3 = V_{OUT} at 10 mV/division, Ch4 = I_{OUT} at 10 A/division

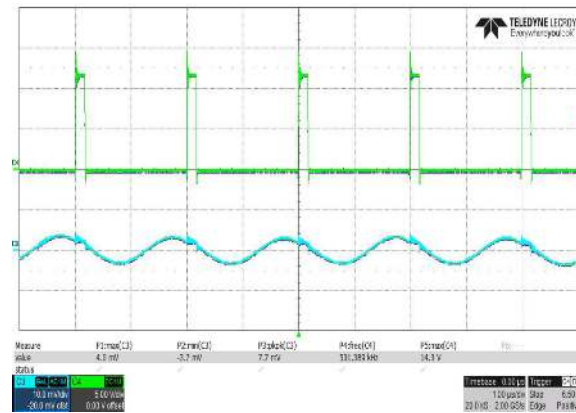
Figure 8. Transient Response of 0.9-V Output at 12 V_{IN}, Transient is 10 A to 30 A, 0.2 A/μs

7.5 Output Ripple



Ch3 = V_{OUT} ripple at 10 mV/division, Ch4 = SW at 5 V/division,

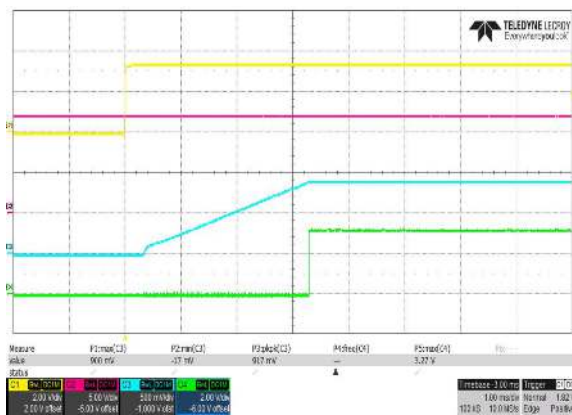
Figure 9. Output Ripple and SW Node of 0.9-V Output at 12 V_{IN}, 0-A Output



Ch3 = V_{OUT} ripple at 10 mV/division, Ch4 = SW at 5 V/division,

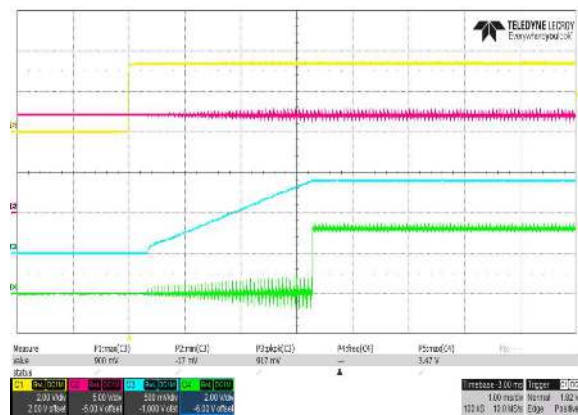
Figure 10. Output Ripple and SW Node of 0.9-V Output at 12 V_{IN} , 35-A Output

7.6 Control On



Ch1 = CNTL at 2 V/division, Ch2 = V_{IN} at 5 V/division, Ch3 = V_{OUT} at 500 mV/division, Ch4 = PGOOD at 2 V/division

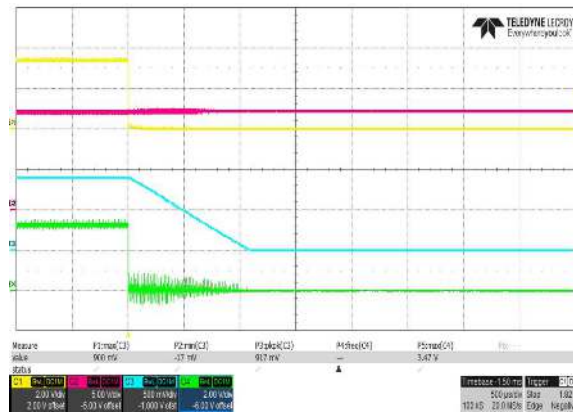
Figure 11. Start up from Control, 0.9-V Output at 12 V_{IN} , 0-A Output



Ch1 = CNTL at 2 V/division, Ch2 = V_{IN} at 5 V/division, Ch3 = V_{OUT} at 500 mV/division, Ch4 = PGOOD at 2 V/division

Figure 12. Start up from Control, 0.9-V Output at 12 V_{IN} , 35-A Output

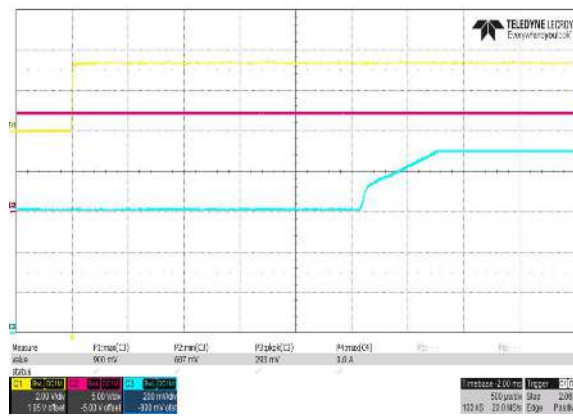
7.7 Control Off



Ch1 = V_{IN} at 10 V/division, Ch2 = CNTL at 2 V/division, Ch3 = V_{OUT} at 500 mV/division, Ch4 = PGOOD at 5 V/division

Figure 13. Soft Stop from Control, 0.9-V Output at 12 V_{IN} , 35-A Output

7.8 Control On under Pre-bias



Ch1 = CNTL at 2 V/division, Ch2 = V_{IN} at 5 V/division, Ch3 = V_{OUT} at 200 mV/division

Figure 14. 0.6-V Pre-bias start up from Control, 0.9-V Output at 12 V_{IN} , 0-A Output

7.9 Overcurrent Protection



Ch2 = V_{IN} at 5 V/division, Ch3 = V_{OUT} at 500 mV/division, Ch4 = I_{OUT} at 10 A/division

Figure 15. Overcurrent Protection, 0.9-V Output at 12 V_{IN} , 35-A Output (OC_Fault threshold is modified to 35A)

7.10 Control Loop Bode Plot

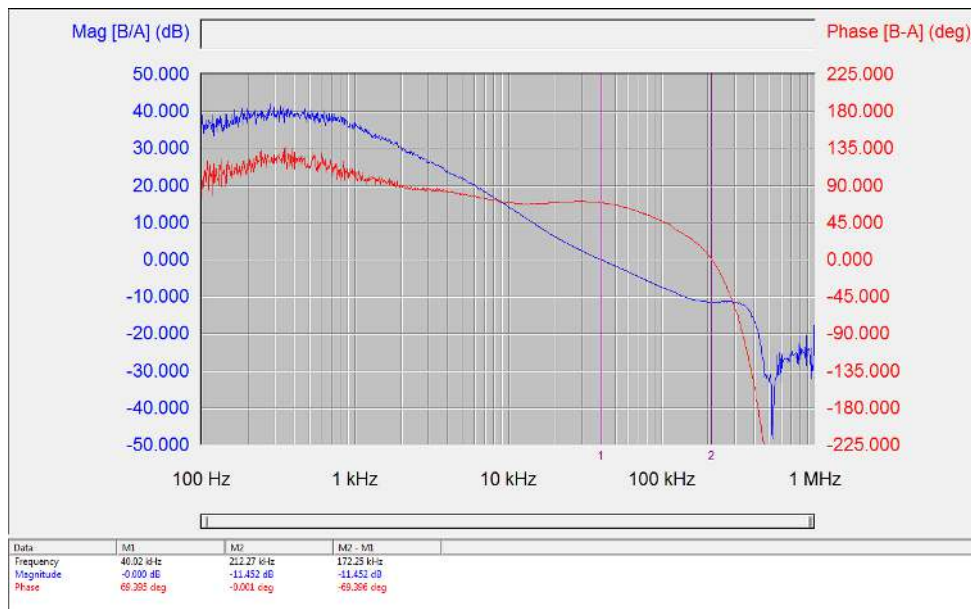


Figure 16. Bode Plot at 0.9-V Output at 12 V_{IN} , 0-A Output

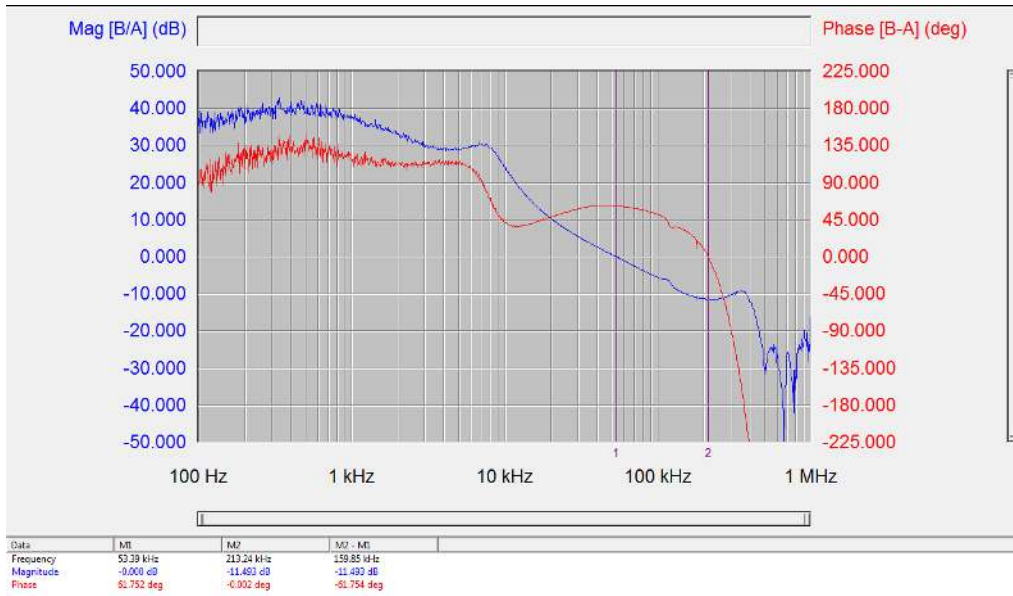
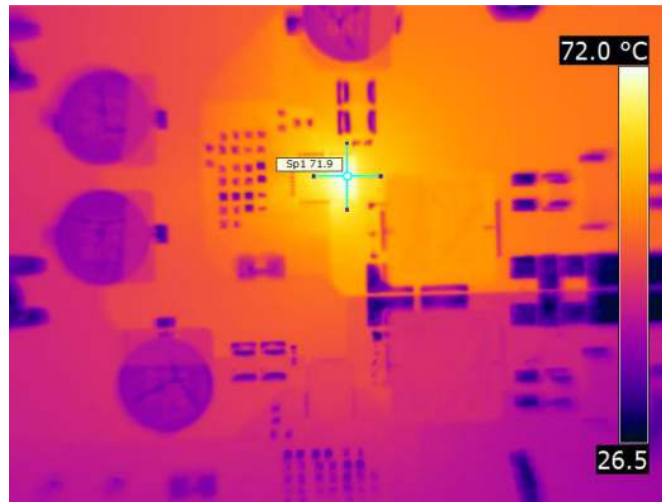


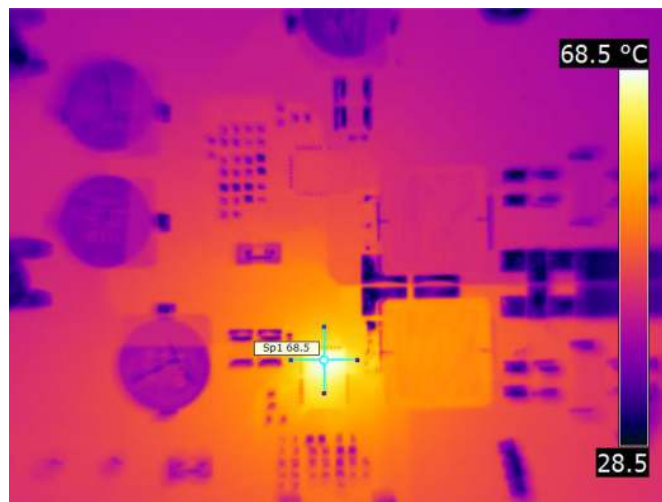
Figure 17. Bode Plot at 0.9-V Output at 12 V_{IN}, 35-A Output

7.11 Thermal Image



$V_{IN} = 12\text{ V}$, $I_{OUT1} = 35\text{ A}$, $V_{OUT1} = 0.9\text{ V}$, $F_{SW} = 500\text{ kHz}$

Figure 18. Thermal Image



$V_{IN} = 12\text{ V}$, $I_{OUT2} = 0\text{ A}$, $V_{OUT2} = 0.95\text{ V}$, $F_{SW} = 500\text{ kHz}$

Figure 19. Thermal Image

8 EVM Assembly Drawing and PCB Layout

Figure 20 through Figure 28 show the design of the TPS546C20AEM1-746 EVM printed circuit board.

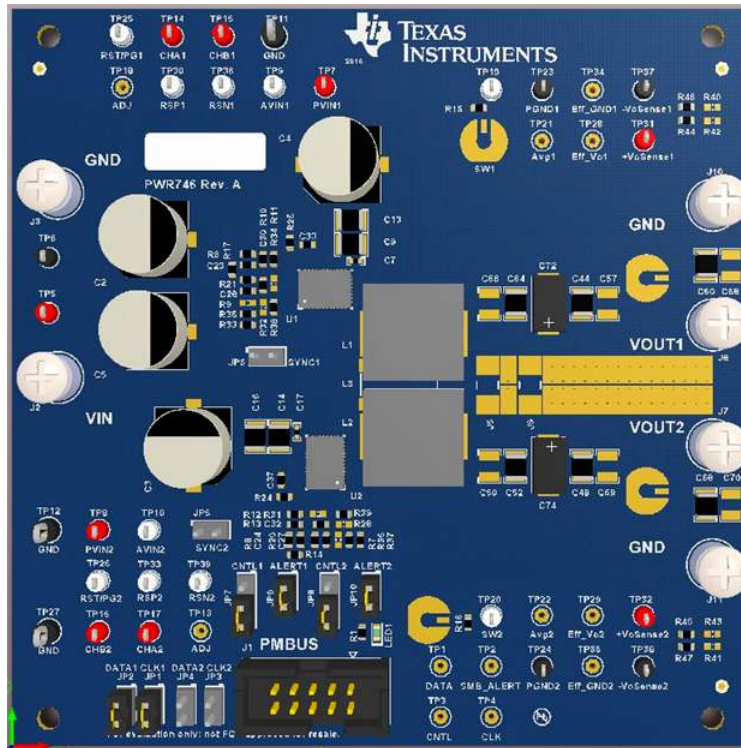


Figure 20. TPS546C20AEM1-746 EVM 3D Top View

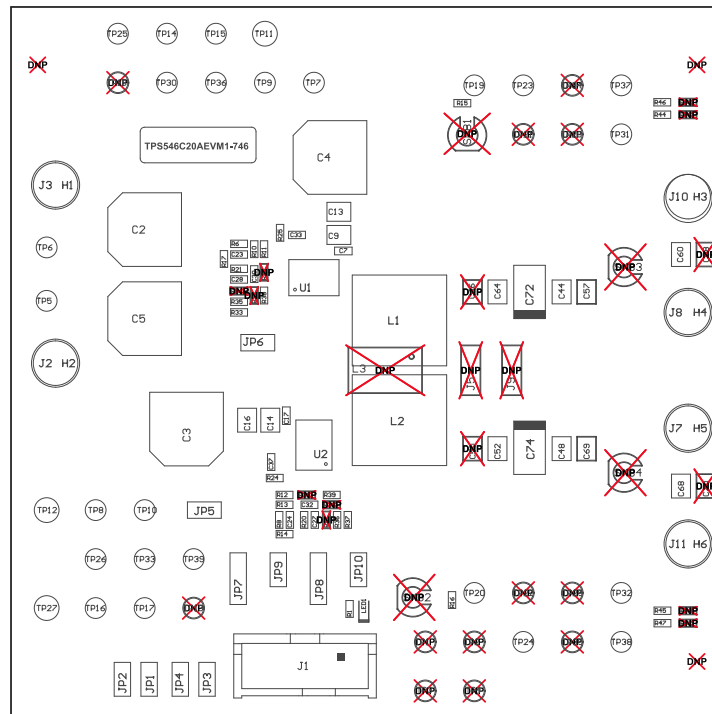


Figure 21. TPS546C20AEM1-746 EVM Top Layer Assembly Drawing (Top View)

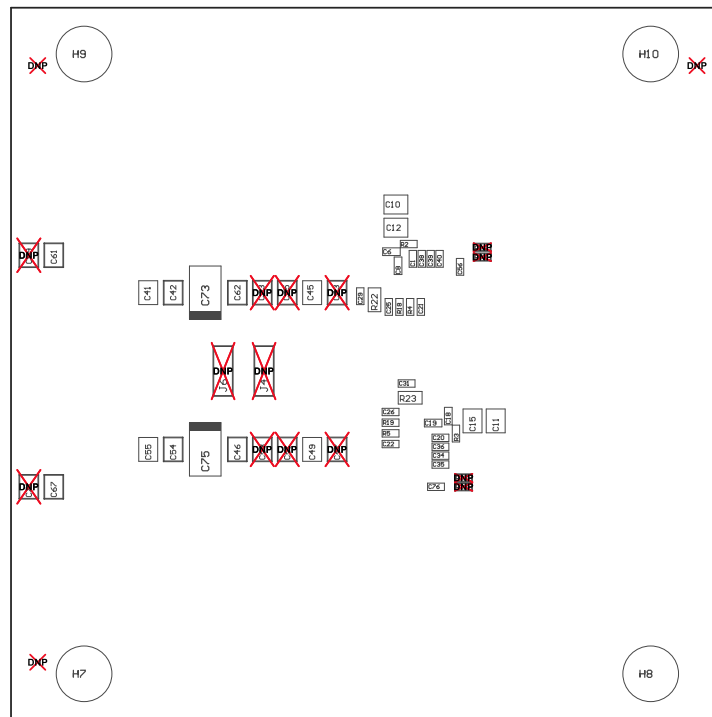


Figure 22. TPS546C20AEVM1-746 EVM Bottom Assembly Drawing (Bottom View)

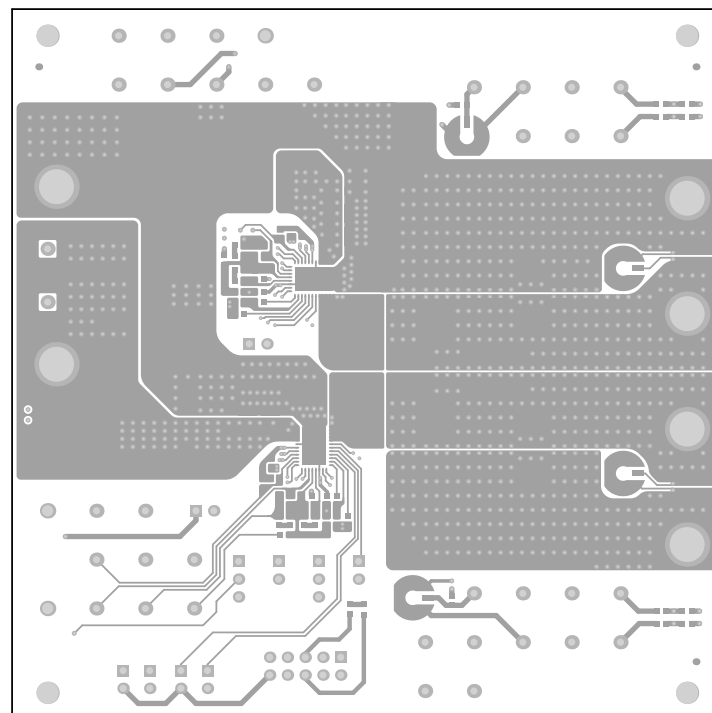


Figure 23. TPS546C20AEVM1-746 EVM Top Copper (Top View)

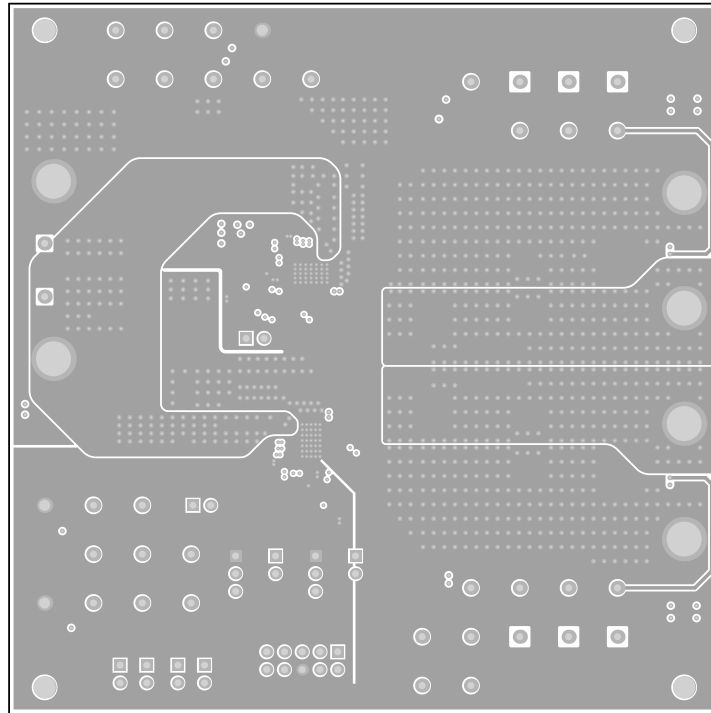


Figure 24. TPS546C20AEVM1-746 EVM Internal Layer 1 (Top View)

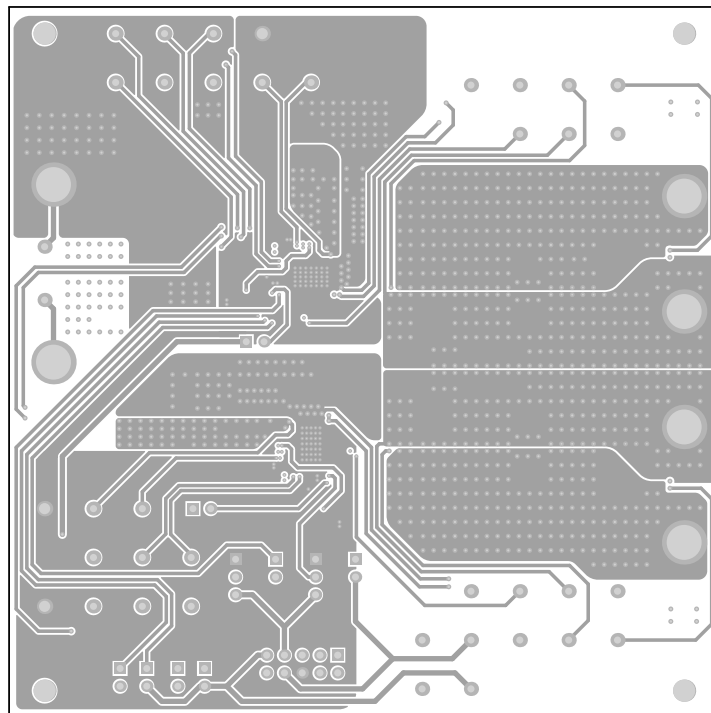


Figure 25. TPS546C20AEVM1-746 EVM Internal Layer 2 (Top View)

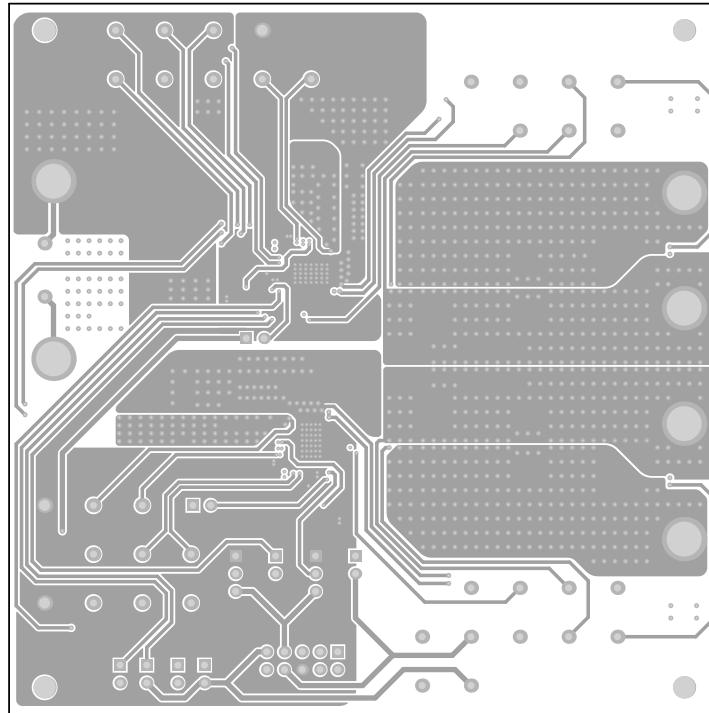


Figure 26. TPS546C20AEVM1-746 EVM Internal Layer 3 (Top View)

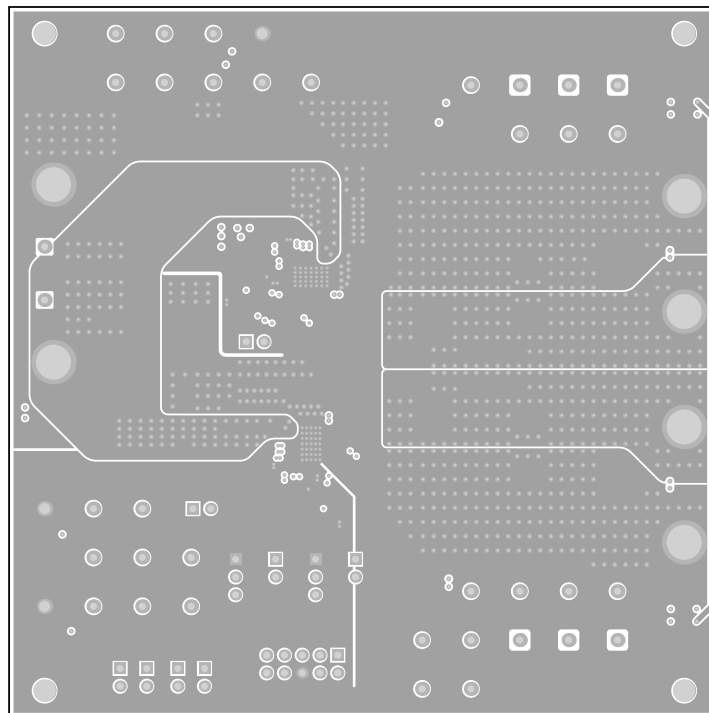


Figure 27. TPS546C20AEVM1-746 EVM Internal Layer 4 (Top View)

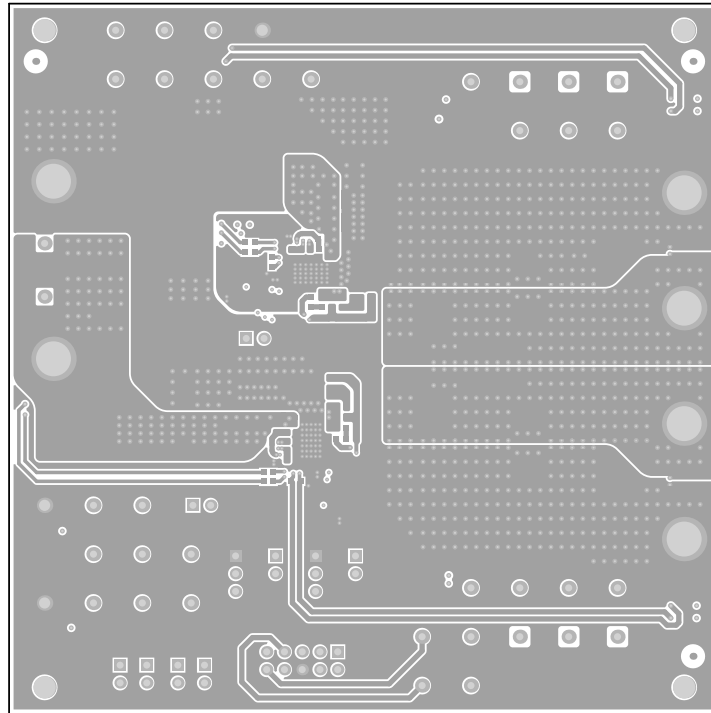


Figure 28. TPS546C20AEVM1-746 EVM Bottom Copper (Top View)

9 Bill of Materials

Table 8 lists the BOM for the TPS546C20AEVM1-746 (TPS546C20A EVM).

Table 8. TPS546C20AEVM1-746 Components List

| Qty | Designator | Description | Part Number | Manufacturer |
|-----|---|--|---------------------|---------------------|
| 4 | C1, C20, C29, C31 | CAP, CERM, 1 µF, 25 V, +/- 10%, X7R, 0603 | GRM188R71E105KA12D | MuRata |
| 4 | C2, C3, C4, C5 | CAP, AL, 100 µF, 35 V, +/- 20%, 0.15 ohm, SMD | EEE-FC1V101P | Panasonic |
| 6 | C6, C7, C8, C17, C18, C19 | CAP, CERM, 6800 pF, 50 V, +/- 10%, X7R, 0402 | GRM155R71H682KA88D | MuRata |
| 8 | C9, C10, C11, C12, C13, C14, C15, C16 | CAP, CERM, 22 µF, 25 V, +/- 10%, X6S, 1210 | GRM32EC81E226KE15L | MuRata |
| 2 | C21, C22 | CAP, CERM, 0.1 µF, 50 V, +/- 10%, X7R, 0603 | C0603C104K5RACTU | Kemet |
| 2 | C23, C24 | CAP, CERM, 1200 pF, 100 V, +/- 5%, C0G/NP0, 0603 | GRM1885C2A122JA01D | MuRata |
| 2 | C25, C26 | CAP, CERM, 1000 pF, 100 V, +/- 5%, X7R, 0603 | 06031C102JAT2A | AVX |
| 2 | C27, C28 | CAP, CERM, 1500 pF, 50 V, +/- 5%, C0G/NP0, 0603 | GRM1885C1H152JA01D | MuRata |
| 2 | C30, C32 | CAP, CERM, 150 pF, 50 V, +/- 5%, C0G/NP0, 0603 | GRM1885C1H151JA01D | MuRata |
| 4 | C33, C36, C37, C38 | CAP, CERM, 2.2 µF, 16 V, +/- 10%, X7R, 0603 | GRM188Z71C225KE43 | MuRata |
| 2 | C34, C39 | CAP, CERM, 4.7 µF, 10 V, +/- 10%, X5R, 0603 | C0603C475K8PACTU | Kemet |
| 2 | C35, C40 | CAP, CERM, 0.1 µF, 16 V, +/- 10%, X7R, 0603 | C0603C104K4RACTU | Kemet |
| 10 | C41, C44, C45, C48, C49, C52, C55, C60, C64, C68 | CAP, CERM, 47 µF, 10 V, +/- 10%, X7R, 1210 | GRM32ER71A476KE15L | MuRata |
| 2 | C56, C76 | CAP, CERM, 330 pF, 50 V, +/- 1%, C0G/NP0, 0603 | C1608C0G1H331F080AA | TDK |
| 4 | C72, C73, C74, C75 | CAP, Tantalum Polymer, 470 µF, 6.3 V, +/- 20%, 0.01 ohm, 7343-40 SMD | 6TPF470MAH | Panasonic |
| 6 | H1, H2, H3, H4, H5, H6 | MACHINE SCREW PAN PHILLIPS 6-32 | PMSSS 632 0038 PH | B&F Fastener Supply |
| 4 | H7, H8, H9, H10 | Bumpon, Cylindrical, 0.312 X 0.200, Black | SJ61A1 | 3M |
| 1 | J1 | Header (shrouded), 100mil, 5x2, Gold, TH | 5103308-1 | TE Connectivity |
| 6 | J2, J3, J7, J8, J10, J11 | Swage Threaded Standoff, Brass, Swage Mount, TH | 1546 | Keystone |
| 8 | JP1, JP2, JP3, JP4, JP5, JP6, JP9, JP10 | Header, 100mil, 2x1, Tin, TH | 5-146278-2 | TE Connectivity |
| 2 | JP7, JP8 | Header, 100mil, 3x1, Tin, TH | 5-146278-3 | TE Connectivity |
| 2 | L1, L2 | Inductor, Shielded, Ferrite, 300 nH, 52 A, 0.00015 ohm, SMD | SLC1480-301MLB | Coilcraft |
| 1 | LBL1 | Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll | THT-14-423-10 | Brady |
| 1 | LED1 | LED, Green, SMD | 150060GS75000 | Wurth Elektronik |
| 1 | R1 | RES, 1.00 k, 1%, 0.1 W, 0603 | CRCW06031K00FKEA | Vishay-Dale |
| 4 | R2, R3, R4, R5 | RES, 0, 5%, 0.1 W, 0603 | ERJ-3GEY0R00V | Panasonic |
| 2 | R6, R8 | RES, 1.10 k, 1%, 0.1 W, 0603 | RC0603FR-071K1L | Yageo America |
| 2 | R10, R13 | RES, 10.0 k, 0.1%, 0.1 W, 0603 | RT0603BRD0710KL | Yageo America |
| 8 | R11, R12, R15, R16, R44, R45, R46, R47 | RES, 49.9, 1%, 0.1 W, 0603 | CRCW060349R9FKEA | Vishay-Dale |
| 8 | R14, R17, R18, R19, R20, R21, R24, R25 | RES, 10.0 k, 1%, 0.1 W, 0603 | RC0603FR-0710KL | Yageo America |
| 2 | R22, R23 | RES, 1.0, 5%, 0.25 W, 1206 | CRCW12061R00JNEA | Vishay-Dale |
| 2 | R33, R35 | RES, 34.8 k, 1%, 0.1 W, 0603 | RC0603FR-0734K8L | Yageo America |
| 2 | R36, R37 | RES, 51.1 k, 1%, 0.1 W, 0603 | RC0603FR-0751K1L | Yageo America |
| 2 | R38, R39 | RES, 40.2 k, 1%, 0.1 W, 0603 | CRCW060340K2FKEA | Vishay-Dale |
| 6 | SH-JP1, SH-JP2, SH-JP7, SH-JP8, SH-JP9, SH-JP10 | Shunt, 100mil, Gold plated, Black | 969102-0000-DA | 3M |
| 1 | TP5 | Test Point, Miniature, Red, TH | 5000 | Keystone |
| 3 | TP6, TP23, TP24 | Test Point, Miniature, Black, TH | 5001 | Keystone |
| 8 | TP7, TP8, TP14, TP15, TP16, TP17, TP31, TP32 | Test Point, Miniature, Red, TH | 5000 | Keystone |
| 10 | TP9, TP10, TP19, TP20, TP25, TP26, TP30, TP33, TP36, TP39 | Test Point, Miniature, White, TH | 5002 | Keystone |
| 3 | TP11, TP12, TP27 | Test Point, Multipurpose, Black, TH | 5011 | Keystone |

Table 8. TPS546C20AEVM1-746 Components List (continued)

| Qty | Designator | Description | Part Number | Manufacturer |
|-----|------------|--|-------------|-------------------|
| 2 | TP37, TP38 | Test Point, Miniature, Black, TH | 5001 | Keystone |
| 2 | U1, U2 | 4.5V-18V, 35A PMBUS STACKABLE SYNCHRONOUS BUCK CONVERTER, RVF0040A | TPS546C20A | Texas Instruments |

10 Screenshots

10.1 Fusion GUI Screenshots

When launching the Fusion GUI, select **IC_DEVICE_ID** in [Figure 29](#) as scanning mode to find TPS546C20A.

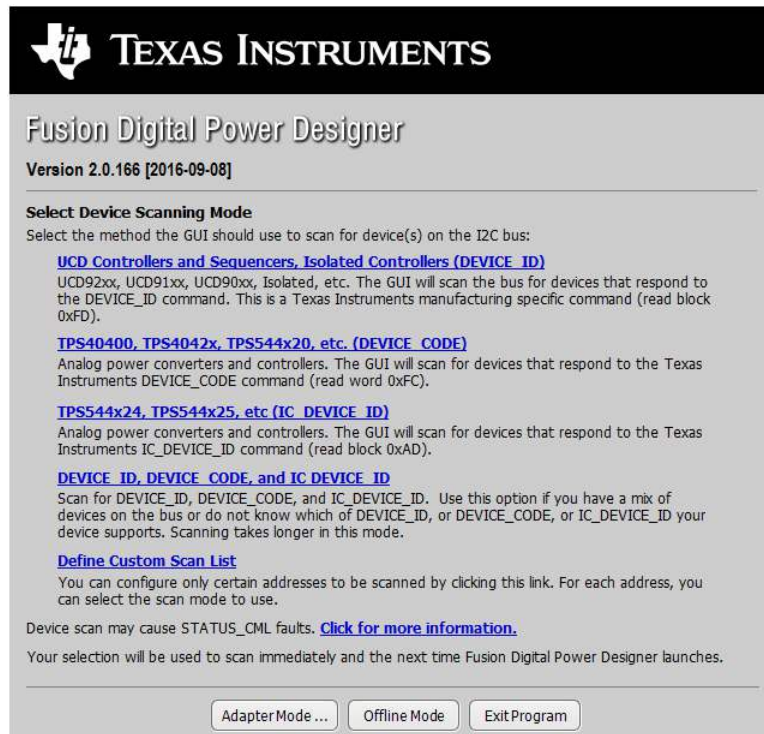


Figure 29. Select Device Scanning Mode

- Use the **Limits & On/Off** tab [Figure 30](#) to configure the following:
 - V_{ref} (Vout_Command)
 - OC Fault and OC Warn
 - OT Fault and OT Warn (Die Temperature)
 - Power Good Limits
 - Fault response
 - UVLO
 - On/Off Config
 - Soft Start time (Turn On Rise)
 - Margin voltage

After making changes to one or more configurable parameters, the changes can be committed to nonvolatile memory by clicking **Store DefaultAll**. This action prompts a *confirm selection* pop-up, and if confirmed, the changes are committed to nonvolatile memory to store all the modifications in non-volatile memory.

For modifications on V_{ref} and Soft Start time, to make the changes effective in next power up, **DIS_VSEL** in **Advanced** tab [Figure 32](#) should be checked and stored to non-volatile memory as well.

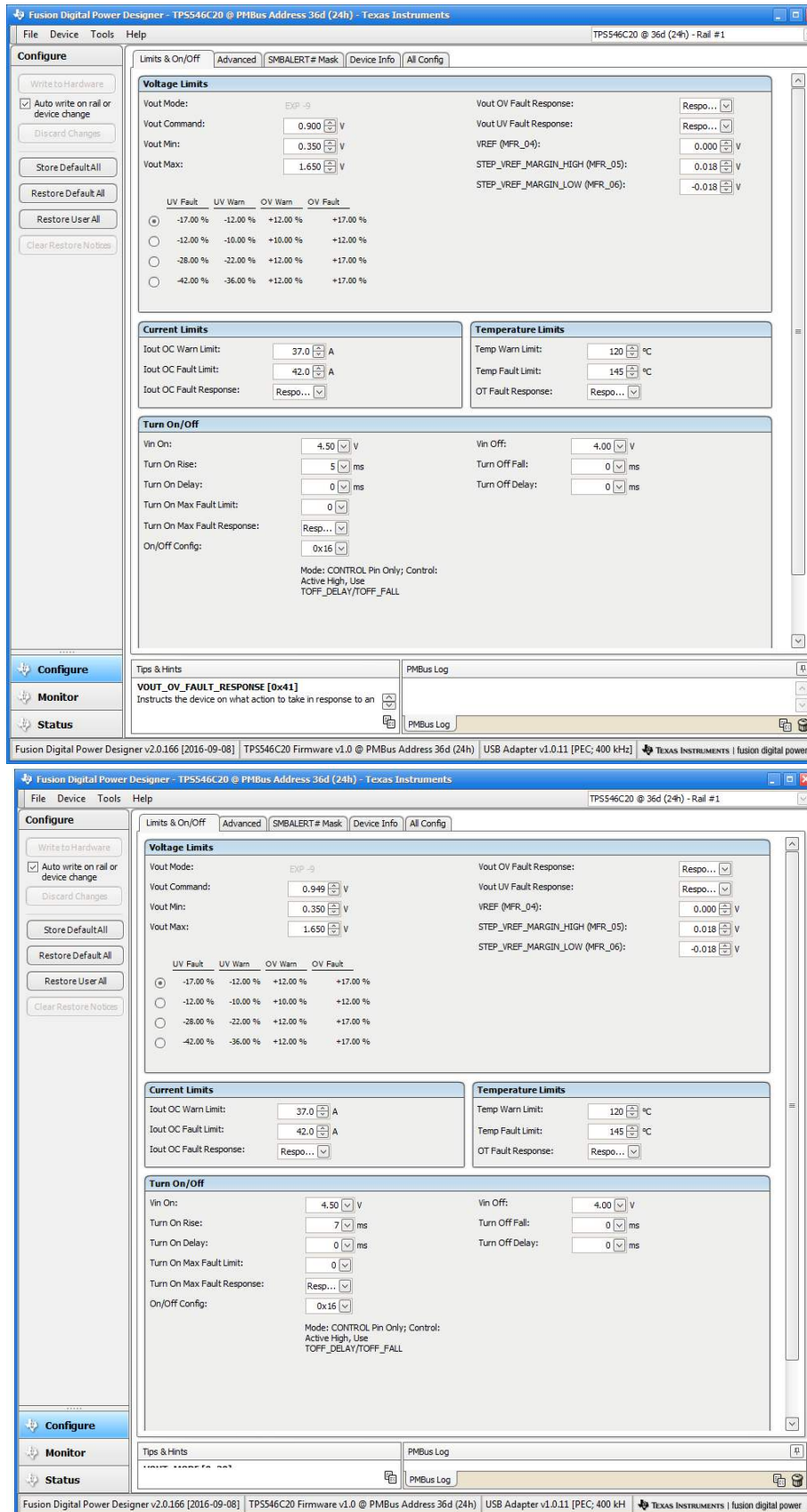


Figure 30. Configure- Limits and On/Off for U1 and U2

Changing the on/off configuration prompts a pop-up window with details of the options [Figure 31](#).

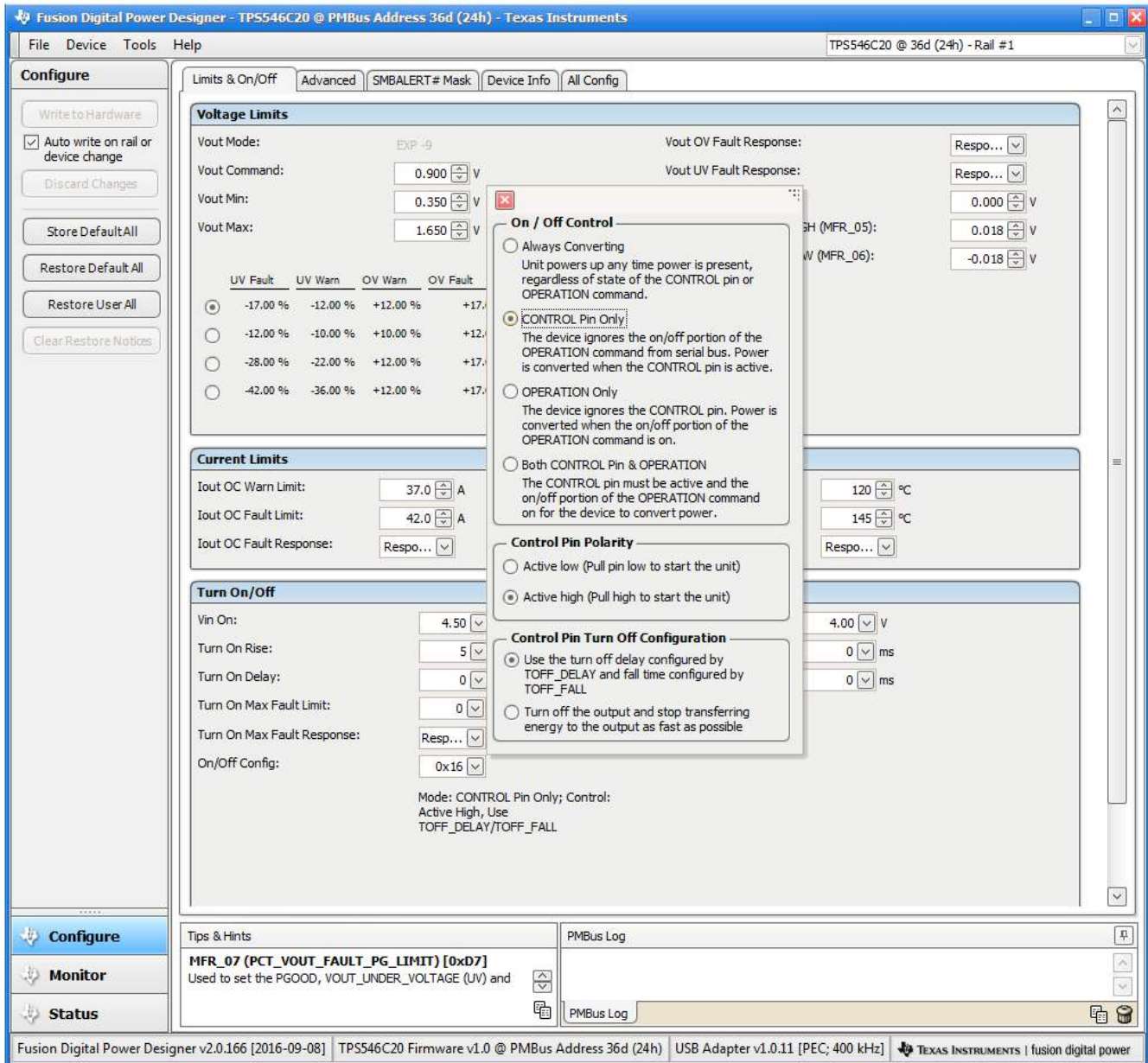


Figure 31. ON/OFF Control Pop-up

- Use the **Advanced** tab [Figure 32](#) to configure:
 - OPTIONS: MFR_SPECIFIC_21 register
 - API_OPTIONS: MFR_SPECIFIC_32 register

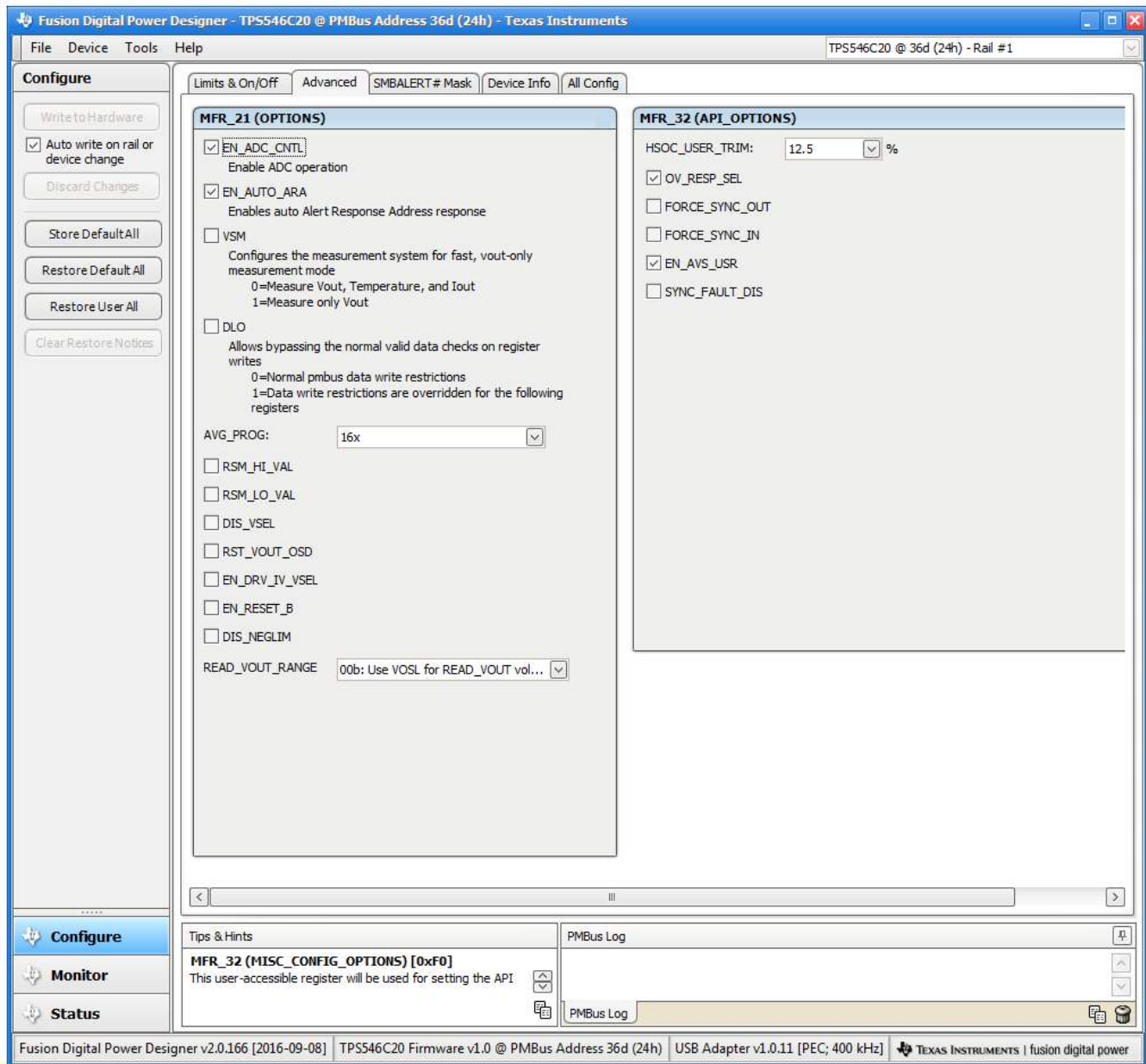


Figure 32. Configure - Advanced

The sources of SMBALERT which can be masked can be found and configured on the **SMBALERT # Mask** tab [Figure 33](#)

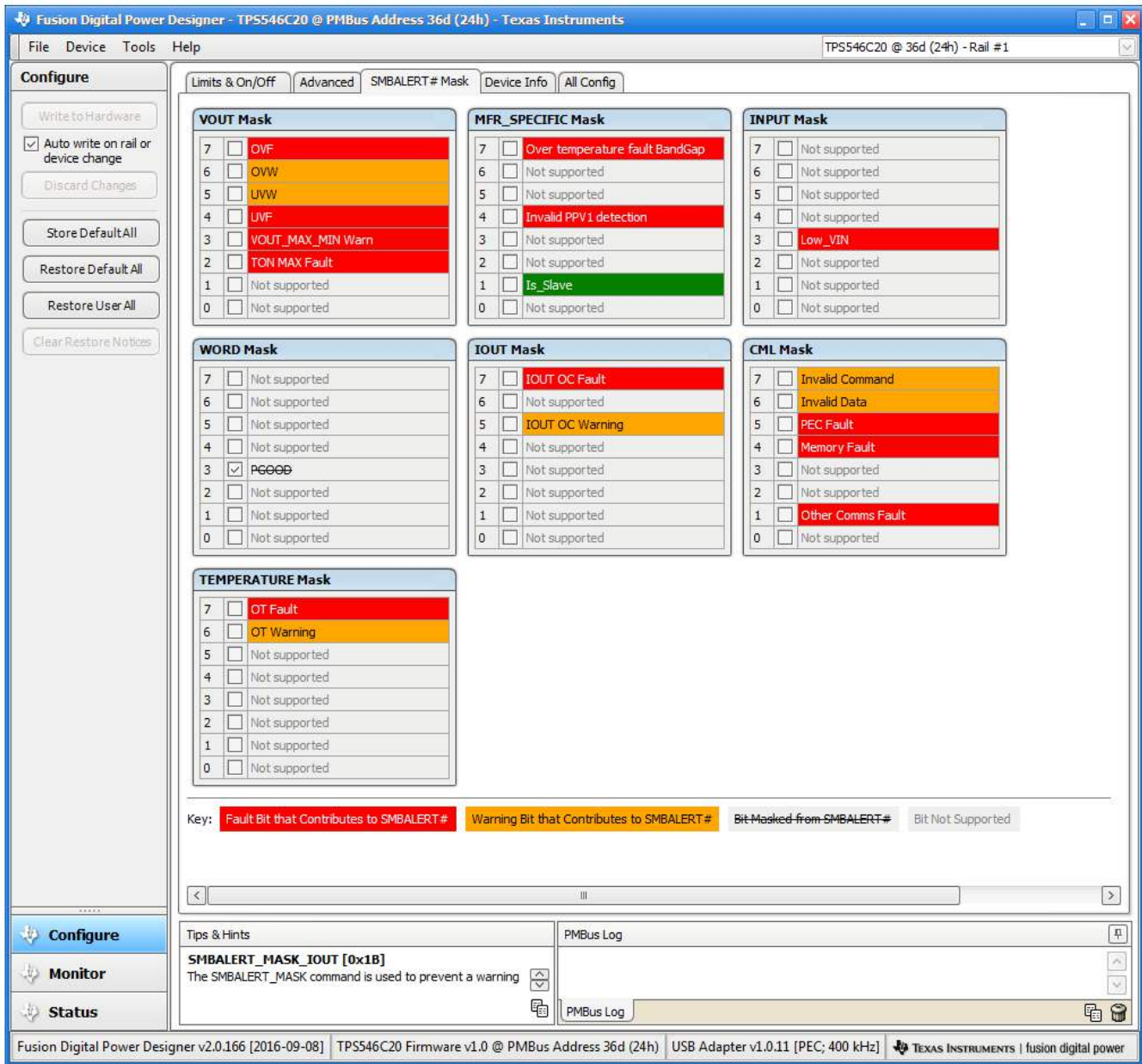


Figure 33. Configure - SMBALERT # Mask

The device information, User Scratch Pad, Write Protection options, the configuration of Vout Scale loop, Vout Transition Rate and Iout Cal Offset can be found on **Device Info** tab [Figure 34](#).

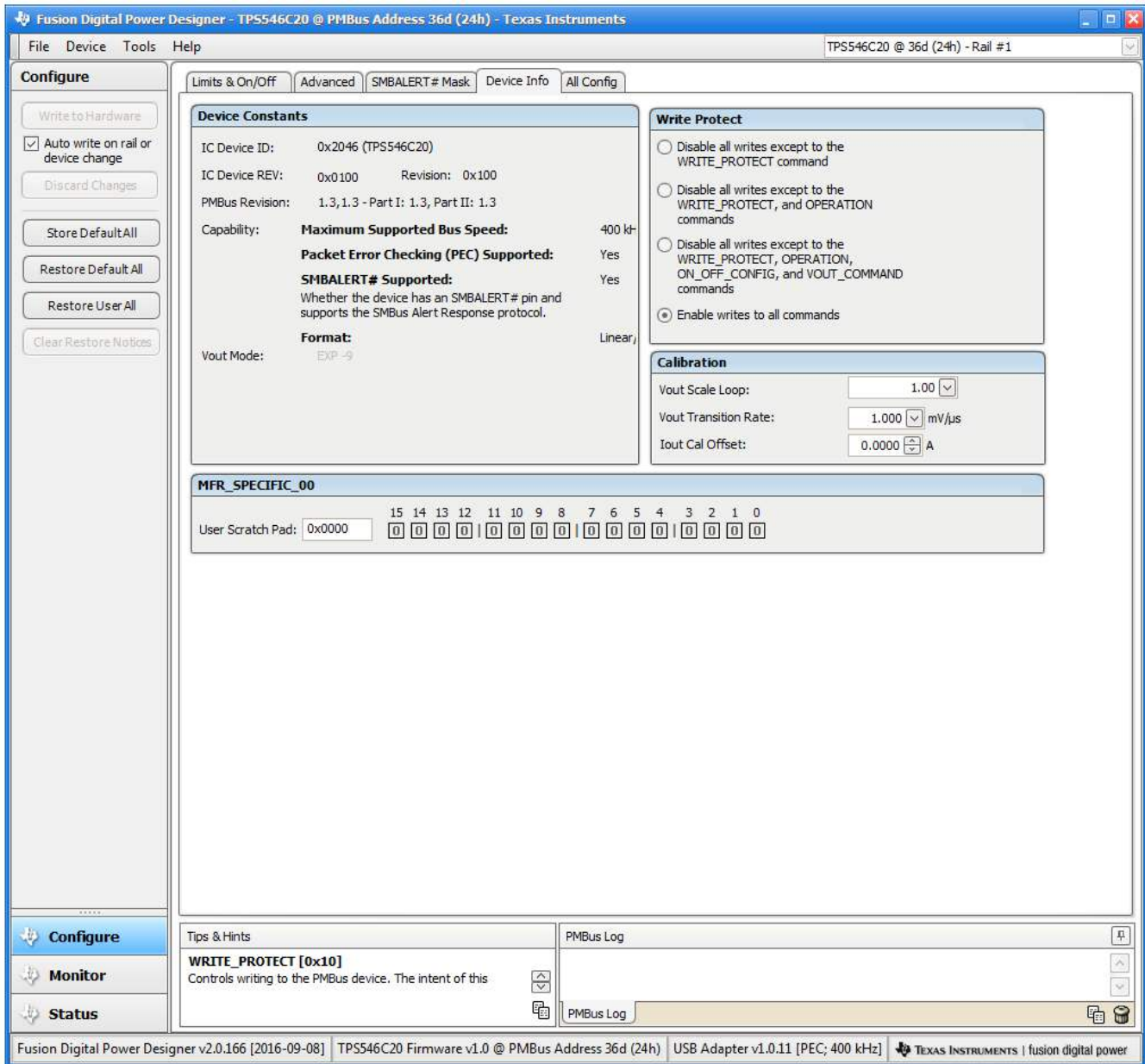


Figure 34. Configure - Device Info

Use the **All Config** tab [Figure 35](#) to configure all of the configurable parameters, which also shows other details like Hex encoding.

The screenshot shows the 'All Config' tab in the Fusion Digital Power Designer software. The interface is divided into several sections:

- Left Panel:** Contains buttons for 'Write to Hardware', 'Auto write on rail or device change', 'Discard Changes', 'Store Default All', 'Restore Default All', 'Restore User All', and 'Clear Restore Notices'. It also has a 'Sort Parameters By:' section with radio buttons for 'Command Name' and 'Command Code', and a checked 'Group by Category' option.
- Main Area:** A large table with columns for 'Command', 'Code', 'Value/Edit', and 'Hex/Edit'. It is organized into several expandable sections:
 - Calibration:** Includes parameters like IOUT_CAL_OFFSET (0x39), MFR_04 (VREF_TRIM) (0xD4), MFR_05 (STEP_VREF_MARGIN_HIGH) (0xD5), MFR_06 (STEP_VREF_MARGIN_LOW) (0xD6), and VOUT_SCALE_LOOP (0x29).
 - Configuration:** Includes parameters like IC_DEVICE_ID (0xAD), IC_DEVICE_REV (0xAE), MFR_21 (OPTIONS) (0xE5), MFR_32 (MISC_CONFIG_OPTIONS) (0xF0), and various SMBALERT_MASK parameters (0x1B).
 - On/Off Configuration:** Includes parameters like ON_OFF_CONFIG (0x02), OPERATION (0x01), TOFF_DELAY (0x64), TOFF_FALL (0x65), TON_DELAY (0x60), TON_MAX_FAULT_LIMIT (0x62), TON_MAX_FAULT_RESPONSE (0x63), and TON_RISE (0x61).
 - Status:** Includes parameters like READ_IOUT (0x8C), READ_TEMPERATURE_1 (0x8D), READ_VOUT (0x8B), STATUS_BYTE (0x78), STATUS_CML (0x7E), STATUS_INPUT (0x7C), STATUS_IOUT (0x7B), STATUS_MFR_SPECIFIC (0x80), STATUS_TEMPERATURE (0x7D), STATUS_VOUT (0x7A), and STATUS_WORD (0x79).
 - User Parameters:** Includes MFR_00 (FOR USER) (0xD0).
- Bottom Panel:** Contains a 'Tips & Hints' section with a tip for 'ON_OFF_CONFIG [0x02]' and a 'PMBus Log' section.
- Footer:** Displays 'Fusion Digital Power Designer v2.0.166 [2016-09-08]', 'TPS546C20 Firmware v1.0 @ PMBus Address 36d (24h)', 'USB Adapter v1.0.11 [PEC; 400 kHz]', and the Texas Instruments logo.

Figure 35. Configure - All Config

When the *Monitor* screen [Figure 36](#) is selected, the screen changes to display real-time data of the parameters that are measured by the device. This screen provides access to:

- Graphs of V_{OUT} , I_{out} , *Temperature*, and *P_{out}*.
- *Start/Stop Polling* which turns ON or OFF the real-time display of data.
- Quick access to On/Off config
- Control pin activation, and OPERATION command.
- Margin control.
- Clear Fault. Selecting **Clear Faults** clears any prior fault flags.

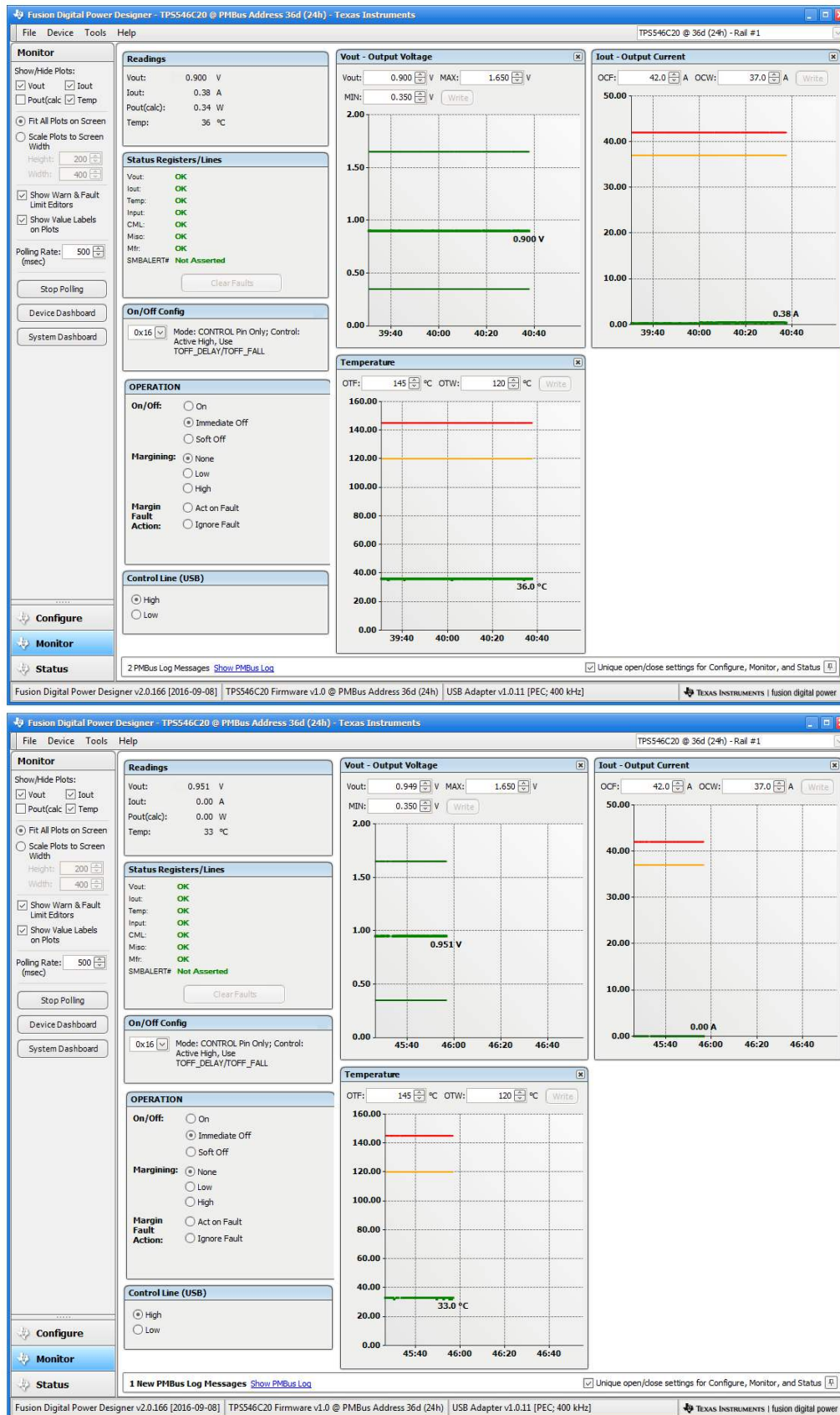


Figure 36. Monitor Screen for U1 and U2

Selecting *Status* screen [Figure 37](#) from lower left corner shows the status of the device .

The screenshot shows the 'Status' screen of the Fusion Digital Power Designer. The interface includes a left sidebar with 'Status', 'Configure', 'Monitor', and 'Status' (highlighted) buttons. The main area displays several status registers:

- STATUS_VOUT:** 7 OVF, 6 OVW, 5 UVW, 4 UVF, 3 VOUT_MAX_MIN Warn, 2 TON MAX Fault, 1 0, 0 0.
- STATUS_IOUT:** 7 IOUT OC Fault, 6 IOUT OC Fault with LV Shutdown, 5 IOUT OC Warning, 4 IOUT UC Fault, 3 Current Share Fault, 2 Power Limiting Mode, 1 POUT OP Fault, 0 POUT OP Warning.
- STATUS_TEMP:** 7 OT Fault, 6 OT Warning, 5 UT Fault, 4 UT Warning, 3 Reserved, 2 Reserved, 1 Reserved, 0 Reserved.
- STATUS_WORD:** 15 VFW, 14 OCFW, 13 INPUT, 12 MFR fault/warn, 11 PGOOD_Z, 10 FANS, 9 OTHER, 8 Unknown, 7 Busy, 6 OFF, 5 OVF, 4 OCF, 3 Vout_MAX_Warning, 2 OTFW, 1 CML, 0 OTH.
- STATUS_CML:** 7 Invalid Command, 6 Invalid Data, 5 PEC Fault, 4 Memory Fault, 3 Processor Fault, 2 Reserved, 1 Other Comms Fault, 0 Other Memory/Logic Fault.
- STATUS_INPUT:** 7 Vin OV Fault, 6 Vin OV Warning, 5 Vin UV Warning, 4 Vin UV Fault, 3 Low_VIN, 2 IIN OC Fault, 1 IIN OC Warning, 0 PIN OP Warning.
- STATUS_FANS_1_2:** 7 Fan 1 Fault, 6 Fan 2 Fault, 5 Fan 1 Warning, 4 Fan 2 Warning, 3 Fan 1 Speed Overridden, 2 Fan 2 Speed Overridden, 1 Air Flow Fault, 0 Air Flow Warning.
- STATUS_FANS_3_4:** 7 Fan 3 Fault, 6 Fan 4 Fault, 5 Fan 3 Warning, 4 Fan 4 Warning, 3 Fan 3 Speed Overridden, 2 Fan 4 Speed Overridden, 1 Reserved, 0 Reserved.
- STATUS_MFR_SPECIFIC:** 7 Over temperature fault Band, 6 FSM Illegal ZERO state, 5 FSM Illegal MANY ONES state, 4 Invalid PPV1 detection, 3 Invalid PPV0 detection, 2 RESET VOUT, 1 Is_Slave, 0 SYNC_FAULT.
- STATUS_OTHER:** 7 Reserved, 6 Reserved, 5 Input A fuse Or circuit breaker fault, 4 Input B fuse or circuit breaker fault, 3 Input A OR-ing device fault, 2 Input B OR-ing device fault, 1 Output OR-ing device fault, 0 Reserved.

A legend at the bottom indicates: Clear Faults, Key: Fault (red), Warning (yellow), See other register (yellow), Bit not set (grey), Bit not implemented (grey). The status bar at the bottom shows: Fusion Digital Power Designer v2.0.166 [2016-09-08] | TPS546C20 Firmware v1.0 @ PMBus Address 36d (24h) | USB Adapter v1.0.11 [PEC; 400 kHz] | TEXAS INSTRUMENTS | fusion digital power

Figure 37. Status Screen

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

| | |
|------------------------------|--|
| Audio | www.ti.com/audio |
| Amplifiers | amplifier.ti.com |
| Data Converters | dataconverter.ti.com |
| DLP® Products | www.dlp.com |
| DSP | dsp.ti.com |
| Clocks and Timers | www.ti.com/clocks |
| Interface | interface.ti.com |
| Logic | logic.ti.com |
| Power Mgmt | power.ti.com |
| Microcontrollers | microcontroller.ti.com |
| RFID | www.ti-rfid.com |
| OMAP Applications Processors | www.ti.com/omap |
| Wireless Connectivity | www.ti.com/wirelessconnectivity |

Applications

| | |
|-------------------------------|--|
| Automotive and Transportation | www.ti.com/automotive |
| Communications and Telecom | www.ti.com/communications |
| Computers and Peripherals | www.ti.com/computers |
| Consumer Electronics | www.ti.com/consumer-apps |
| Energy and Lighting | www.ti.com/energy |
| Industrial | www.ti.com/industrial |
| Medical | www.ti.com/medical |
| Security | www.ti.com/security |
| Space, Avionics and Defense | www.ti.com/space-avionics-defense |
| Video and Imaging | www.ti.com/video |

TI E2E Community

e2e.ti.com